



APPLICATION NOTE

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A Multibus-Compatible 2816 E²PROM Memory Board

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INTRODUCTION

The Intel Special Products Division E² Multibus Memory Board is an excellent example of how to implement the 2816 Electrically Erasable PROM in a multibus system. The board is completely Multibus compatible and can be plugged into any existing Intel Microcomputer Development System. It can also be used in a Multibus-compatible system with any combination of Intel Single-Board Computer (iSBC) Modules. The memory board has a capacity of up to 16K bytes of electrically erasable non-volatile memory storage (8 2816s). The board can be read at microprocessor system speeds (250 ns). Writing to the E² Board requires only a single system write cycle. When the write operation is complete, the E² Board notifies the CPU by lowering an Interrupt Line. Individual 2816s can be erased in a similar manner with one write operation.

The E² Memory Board can operate with either an 8 or a 16-bit-wide data bus. This is determined by one jumper and by a 3628A Bipolar PROM used for decoding the addresses to the MOS PROM Array. The 3628A gives the board the capability of accommodating combinations of 2816s, 2815s, 2716s, 2732s, 2732As, and 2764s. The JEDEC pin compatibility of Intel's MOS EPROMs allows these devices to be plugged into the same 28-pin sockets. The 3628A, used as a decoder, allows these different memory size MOS PROMs to be used in the same array in various combinations. This enables the user to mix the devices in the memory array to fit the system's particular applications. The Multibus card can be located anywhere within up to one Megabyte of addressing space. The V_{PP} supply voltage is generated on board, and the only voltages needed are the standard Multibus +5V, +12V, and -12V power supplies. Finally, the E² memory system can be powered up and down repeatedly without losing one byte of its 16K bytes of data.

INSTALLATION INSTRUCTIONS

Below is a procedure to prepare the E² memory card for use. Following the list are detailed instructions for each step.

Procedure

1. Install the correct shorting plugs on the following jumper groups:

J9-J12

Board Address Location

J13-J19

RESET and Chip Erase I/O Addresses

J1-J8

Interrupt Line Selection

J20

Data Bus Width

J21-J24

PROM Socket Address Configuration

JW1-JW8

PROM/RAM Selection

2. V_{PP} Pulse Width Selection

3. Set switches SW1-SW5 according to the MOS PROM density used.

4. Adjust the V_{PP} high voltage level.

5. Select the proper X_{ACK} delay based on the t_{ACC} of the slowest MOS PROM used.

Board Address Location

The E² board can be assigned to any one of the 16 64K byte pages within a one-megabyte address space. If only 64K of address space is available, leave the jumper pairs J9-J12 open. Otherwise, install the shorting plugs to select the desired page as shown in the following chart:

Board Address Selection

X = install shorting plug

O = open

As shown in the assembly drawing in Appendix D, 2 pins reside at each jumper location. A shorting plug is simply inserted at the jumper location for installation.

64K Page	Jumper			
	J12	J11	J10	J9
0K- 64K	O	O	O	O
64K- 128K	O	O	O	X
128K- 192K	O	O	X	O
192K- 256K	O	O	X	X
256K- 320K	O	X	O	O
320K- 384K	O	X	O	X
384K- 448K	O	X	X	O
448K- 512K	O	X	X	X
512K- 576K	X	O	O	O
576K- 640K	X	O	O	X
640K- 704K	X	O	X	O
704K- 768K	X	O	X	X
768K- 832K	X	X	O	O
832K- 896K	X	X	O	X
896K- 960K	X	X	X	O
960K-1024K	X	X	X	X

RESET and Chip Erase Functions

The board requires two consecutive I/O addresses to control the RESET and Chip Erase functions. Doing an

I/O write cycle to one or the other address activates the particular function. The even I/O address selects the RESET function, an odd I/O address sets the Chip Erase function.

Jumper I/O Address bit	J19 A7	J18 A6	J17 A5	J16 A4	J15 A3	J14 A2	J13 A1	A0
Function	RESET	b	b	b	b	b	b	0
	Chip Erase Mode	b	b	b	b	b	b	1
b = address bit								

Once two consecutive I/O addresses for these two functions are determined, then install shorting plugs on J13–J19 corresponding to the 1's in the upper 7 bits of the two I/O addresses.

Examples:

for 00H = RESET

01H = Chip Erase,
install *no* shorting plugs

for 8AH = RESET

8BH = Chip Erase,
put shorting plugs on J13, J15, and J19

for 32H = RESET

33H = Chip Erase
put shorting plugs on J13, J16, J17

Interrupt Line Selection

The E² Memory Board generates an interrupt upon completion of a Byte Erase/Write or a Chip Erase operation. Any one of the 8 Multibus Interrupt Lines can be used. To select a given Interrupt Line, install the shorting plug indicated below:

Interrupt Line	Jumper
INT 0	J1
INT 1	J2
INT 2	J3
INT 3	J4
INT 4	J5
INT 5	J6
INT 6	J7
INT 7	J8

Data Bus Width

The Multibus Card can use either an 8-bit or a 16-bit-wide data bus. Jumper J20 should be installed for 16-bit data buses, and left open for 8-bit-wide buses.

In addition, switches SW1–SW5 must be set so that the correct MOS PROM(s) are enabled for upper and/or lower byte operations. Refer to the 16-Bit Data Bus

Jumpers J13 through J19 determine which two consecutive I/O addresses are to be used. The following chart shows the jumper scheme for I/O addressing.

Structure section for an explanation of the E² Board internal data bus structure. Refer to the following PROM Array Decoder subsection for directions on setting switches SW1–SW5.

PROM/RAM Selection

If E²PROMs or EPROMs are used in the MOS PROM Array, do the following:

Install shorting plugs on the following jumpers:

JW1, JW3, and JW8

Leave these jumpers OPEN:

JW2, JW4, JW5, JW6, and JW7

V_{PP} PULSE WIDTH SELECTION

Ensure that the correct RC timing components are installed for the E²PROM to be used:

E ² PROM	R3	C8	t _{wp}
2816	10 K Ω	4.7 μ F	10 ms
2815	24 K Ω	10 μ F	50 ms

R3 and C8 are located at the top and center of the E² board on the left of I.C. H1.

MOS PROM Array Decoder

(See Figure 1) The Bipolar PROM is used to select the MOS PROM or MOS PROM pair being addressed. The Bipolar PROM holds decoding algorithms for 2816s, 2815s, 2716s, 2732s, 2732As, and 2764s. The decoder also selects one or two devices at a time depending on whether an 8-bit or a 16-bit data bus is being used. The Dipswitch at the top of the board determines which decoding algorithm is to be used. Use Table 1 to choose the proper switch setting for the MOS PROMs to be loaded in the Array. The correct shorting plugs must also be installed on Jumpers J21–J24—see Table 2.

If it is desired to have devices of different densities in the Array or if a decoding algorithm other than the one provided is needed, the spare blocks in the 3628A can

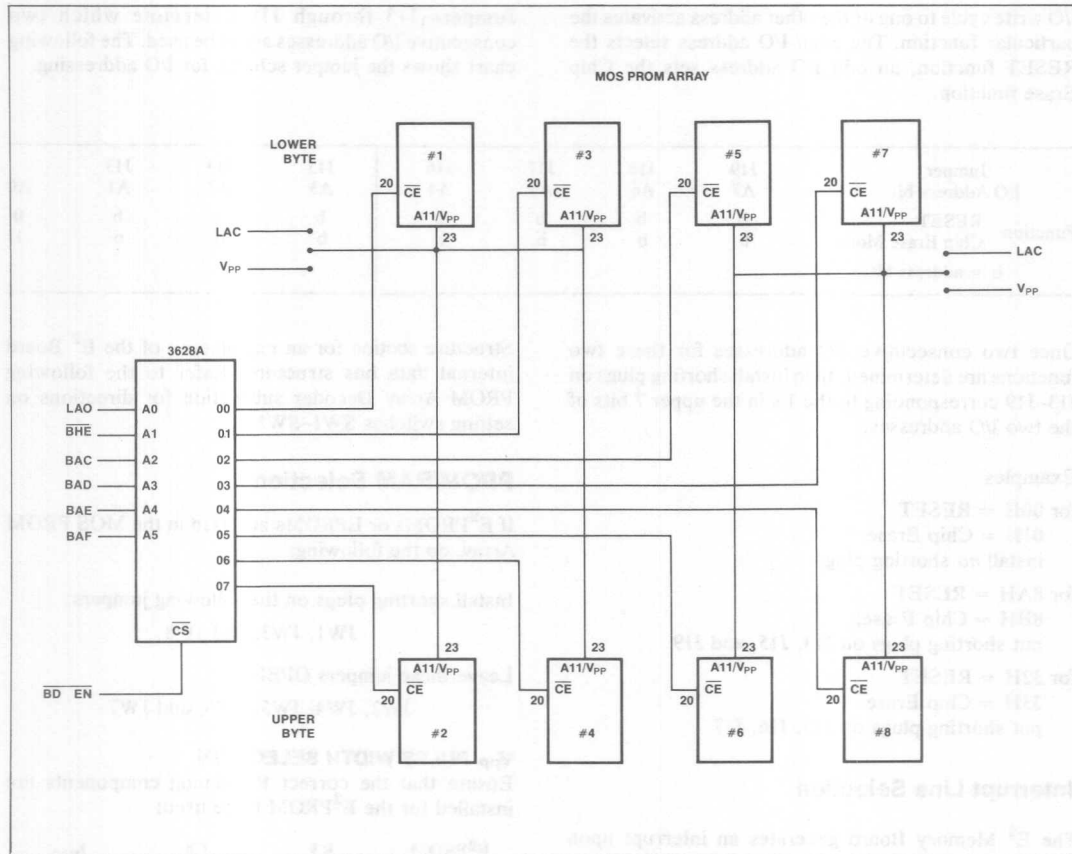


Figure 1. PROM Array Address Configuration

be programmed with new algorithms. The structure of the algorithm is determined by a simple principle. The output corresponding to the $\overline{\text{CE}}$ of the MOS PROM to be selected should be a logic 0 for the address range of that PROM. The selecting addresses are A12, A13, A14, A15 (called BAC-BAF on the schematic), and A0 and $\overline{\text{BHE}}$. (See section on 16-Bit Data Bus Structure for information on the use of A0 and $\overline{\text{BHE}}$.) The smallest address range is 2K bytes. Addresses A12-A15 select a pair of PROMs while A0/ $\overline{\text{BHE}}$ select one or both of the two PROMs in that pair. Figures 2 through 7 can be used as examples. (Also see Appendix B.)

The decoding algorithms must also take into account the data bus width. See figures 2 through 4 for examples of 8-bit data bus algorithms and figures 5 through 7 for examples of 16-bit data bus algorithms. Note that the proper shorting plugs must be installed on Jumpers J21–J24 according to the device densities used.

Jumpers J21–J24 simply connect address A11 or V_{PP} to pin 23 of the 28-pin MOS PROM socket. If a given Array half (sockets 1–4, for example) is to be loaded with 2816s or 2716s, then V_{PP} must go to pin 23 (Jumpers J22 and J24). If 4K or 8K byte parts are used, then A11 must be connected to pin 23 (Jumpers J21 and J22).

A few rules must be followed in mixed-density Arrays. (1) Each socket pair (1 and 2, 3 and 4, etc.: see Figure 1) must contain devices of the same density. (2) Each Array half (sockets 1–4 and sockets 5–8) can contain either 4K and 8K pairs, or 2K pairs, but not both.

If desired, a 3636B can be used instead of a 3628A. The 2K X 8 3636B will allow the encoding of twice as many decoding algorithms as the 1K X 8 3628A.

The blank PROM Decoder charts in Appendix G may be helpful in planning new decoding algorithms.

SYSTEM ADDRESS A0-15 HEX	DECODER CIRCUIT INPUTS						CE'S								BYTE
	BAF	BAE	BAD	BAC	BHEN	LA0	7	6	5	4	3	2	1	0	
0 X X X	0	0	0	0	1	0							0	0	L H
1 X X X	0	0	0	1	1	0					0	0			L H
2 X X X	0	0	1	0	1	0			0	0					L H
3 X X X	0	0	1	1	1	0		0							L H
4 X X X	0	1	0	0	1	0									L H
5 X X X	0	1	0	1	1	0									L H
6 X X X	0	1	1	0	1	0									L H
7 X X X	0	1	1	1	1	0									L H
8 X X X	1	0	0	0	1	0									L H
9 X X X	1	0	0	1	1	0									L H
A X X X	1	0	1	0	1	0									L H
B X X X	1	0	1	1	1	0									L H
C X X X	1	1	0	0	1	0									L H
D X X X	1	1	0	1	1	0									L H
E X X X	1	1	1	0	1	0									L H
F X X X	1	1	1	1	1	0									L H
X=HEX DIGITS	A5	A4	A3	A2	A1	A0	0	0	0	0	0	0	0	0	
ADDRESS INPUTS 3628A							OUTPUTS								

L = LOW BYTE
H = HIGH BYTE

0 = ENABLE
1 = DISABLE

0 = NO SHORTING PLUG
X = SHORTING PLUG INSTALLED

8 BIT DATA BUS

LEAVE JUMPER J20 OPEN. (NO SHORTING PLUG)

INSTALL SHORTING PLUGS
PER THE FOLLOWING TABLE:

DEVICE DENSITY = 2K BYTES

		JUMPERS			
		PROMS:			
		1-4		5-8	
		J21	J22	J23	J24
2K		0	X	0	X
4K/8K		X	0	X	0

Figure 2. 2716 or 2816

Table 1. BIP Decoder Switch Settings

Device		2816/2815/2716		2732/2732A	2764
Address Range in Hex (For Full Array)		0000-3FFF	8000-BFFF	0000-7FFF	0000-FFFF
8-Bit Data Bus	SW1	ON	ON	OFF	ON
	SW2	ON	OFF	OFF	OFF
	SW3	ON	OFF	ON	ON
	SW4	ON	ON	ON	ON
	*SW5	ON	ON	ON	ON
16-Bit Data Bus	SW1	OFF	OFF	ON	OFF
	SW2	OFF	OFF	ON	ON
	SW3	ON	OFF	OFF	OFF
	SW4	ON	ON	ON	ON
	*SW5	ON	ON	ON	ON

OFF = No shorting plug.

ON = Install shorting plug.

*Must Be "ON" for 3628A.

SYSTEM ADDRESS A0-15 HEX	DECODER CIRCUIT INPUTS						CE'S								BYTE
	BAF	BAE	BAD	BAC	BHEN	LA0	7	6	5	4	3	2	1	0	
0 X X X	0	0	0	0	1	0							0	L	
1 X X X	0	0	0	1	1	0							0	H	
2 X X X	0	0	1	0	1	0					0	0		L	
3 X X X	0	0	1	1	1	0					0	0		H	
4 X X X	0	1	0	0	1	0			0	0				L	
5 X X X	0	1	0	1	1	0			0	0				H	
6 X X X	0	1	1	0	1	0		0						L	
7 X X X	0	1	1	1	1	0		0						H	
8 X X X	1	0	0	0	1	0								L	
9 X X X	1	0	0	1	1	0								H	
A X X X	1	0	1	0	1	0								L	
B X X X	1	0	1	1	1	0								H	
C X X X	1	1	0	0	1	0								L	
D X X X	1	1	0	1	1	0								H	
E X X X	1	1	1	0	1	0								L	
F X X X	1	1	1	1	1	0								H	
X = HEX DIGITS	A5	A4	A3	A2	A1	A0	0	0	0	0	0	0	0	0	
ADDRESS INPUTS 3628A							7	6	5	4	3	2	1	0	
							OUTPUTS								

L = LOW BYTE
H = HIGH BYTE

0 = ENABLE
1 = DISABLE

0 = NO SHORTING PLUG
X = SHORTING PLUG INSTALLED

8 BIT DATA BUS

LEAVE JUMPER J20 OPEN. (NO SHORTING PLUG)

INSTALL SHORTING PLUGS
PER THE FOLLOWING TABLE:

DEVICE DENSITY = 4K BYTES

		JUMPERS			
		PROMS:			
		1-4		5-8	
	J21	J22	J23	J24	
2K	0	X	0	X	
4K/8K	X	0	X	0	

Figure 3. 2732 or 2732A

Table 2. MOS PROM Sockets

Device Density	1-4		5-8	
	J21	J22	J23	J24
2K	O	X	O	X
4K or 8K	X	O	X	O

O = No shorting plug.
X = Install shorting plug.

SYSTEM ADDRESS A0-15 HEX	DECODER CIRCUIT INPUTS						CE'S								BYTE
	BAF	BAE	BAD	BAC	BHEN	LA0	7	6	5	4	3	2	1	0	
0 X X X	0	0	0	0	1	0							0	0	L
1 X X X	0	0	0	1	1	0							0	0	L
2 X X X	0	0	1	0	1	0							0	0	L
3 X X X	0	0	1	1	1	0							0	0	L
4 X X X	0	1	0	0	1	0					0	0			L
5 X X X	0	1	0	1	1	0					0	0			L
6 X X X	0	1	1	0	1	0					0	0			L
7 X X X	0	1	1	1	1	0					0	0			L
8 X X X	1	0	0	0	1	0			0	0					L
9 X X X	1	0	0	1	1	0			0	0					L
A X X X	1	0	1	0	1	0			0	0					L
B X X X	1	0	1	1	1	0			0	0					L
C X X X	1	1	0	0	1	0		0							L
D X X X	1	1	0	1	1	0		0							L
E X X X	1	1	1	0	1	0		0							L
F X X X	1	1	1	1	1	0		0							L
X-HEX DIGITS	A5	A4	A3	A2	A1	A0	0	0	0	0	0	0	0	0	
							7	6	5	4	3	2	1	0	
	ADDRESS INPUTS 3628A						OUTPUTS								

L = LOW BYTE
H = HIGH BYTE

0 = ENABLE
1 = DISABLE

0 = NO SHORTING PLUG
X = SHORTING PLUG INSTALLED

8 BIT DATA BUS

LEAVE JUMPER J20 OPEN, (NO SHORTING PLUG)

INSTALL SHORTING PLUGS
PER THE FOLLOWING TABLE:
DEVICE DENSITY = 8K BYTES

JUMPERS

PROMS:

	1-4		5-8	
	J21	J22	J23	J24
2K	0	X	0	X
4K/8K	X	0	X	0

Figure 4. 2764

SYSTEM ADDRESS A0-15 HEX	DECODER CIRCUIT INPUTS						CE'S								BYTE
	BAF	BAE	BAD	BAC	BHEN	LA0	7	6	5	4	3	2	1	0	
0XXX	0	0	0	0	0 1 0	0 0 1							0 0 0	0 0 0	W L H
1XXX	0	0	0	1	0 1 0	0 0 1						0 0 0	0 0 0		W L H
2XXX	0	0	1	0	0 1 0	0 0 1			0 0 0	0 0 0					W L H
3XXX	0	0	1	1	0 1 0	0 0 1		0 0 0							W L H
4XXX	0	1	0	0	0 1 0	0 0 1									W L H
5XXX	0	1	0	1	0 1 0	0 0 1									W L H
6XXX	0	1	1	0	0 1 0	0 0 1									W L H
7XXX	0	1	1	1	0 1 0	0 0 1									W L H
8XXX	1	0	0	0	0 1 0	0 0 1									W L H
9XXX	1	0	0	1	0 1 0	0 0 1									W L H
AXXX	1	0	1	0	0 1 0	0 0 1									W L H
BXXX	1	0	1	1	0 1 0	0 0 1									W L H
CXXX	1	1	0	0	0 1 0	0 0 1									W L H
DXXX	1	1	0	1	0 1 0	0 0 1									W L H
EXXX	1	1	1	0	0 1 0	0 0 1									W L H
FXXX	1	1	1	1	0 1 0	0 0 1									W L H
	A5	A4	A3	A2	A1	A0	7	6	5	4	3	2	1	0	

X = HEX DIGITS

ADDRESS INPUTS
3628A

OUTPUTS

L = LOW BYTE
H = HIGH BYTE

0 = ENABLE
1 = DISABLE

0 = NO SHORTING PLUG
X = SHORTING PLUG INSTALLED

16 BIT DATA BUS

INSTALL SHORTING PLUG AT JUMPER J20.

INSTALL SHORTING PLUGS
PER THE FOLLOWING TABLE:

DEVICE DENSITY = 2K BYTES

JUMPERS			
PROMS:			
1-4		5-8	
J21	J22	J23	J24
0	X	0	X
2K			
4K/8K	X	0	0

Figure 5. 2716 or 2816

SYSTEM ADDRESS A0-15 HEX	DECODER CIRCUIT INPUTS						CE'S								BYTE
	BAF	BAE	BAD	BAC	BHEN	LA0	7	6	5	4	3	2	1	0	
0XXX	0	0	0	0	0 1 0	0 0 1							0 0 0	0 0 0	W L H
1XXX	0	0	0	1	0 1 0	0 0 1							0 0 0	0 0 0	W L H
2XXX	0	0	1	0	0 1 0	0 0 1						0 0 0	0 0 0		W L H
3XXX	0	0	1	1	0 1 0	0 0 1						0 0 0	0 0 0		W L H
4XXX	0	1	0	0	0 1 0	0 0 1			0 0 0	0 0 0					W L H
5XXX	0	1	0	1	0 1 0	0 0 1			0 0 0	0 0 0					W L H
6XXX	0	1	1	0	0 1 0	0 0 1	0 0 0	0 0 0							W L H
7XXX	0	1	1	1	0 1 0	0 0 1	0 0 0	0 0 0							W L H
8XXX	1	0	0	0	0 1 0	0 0 1									W L H
9XXX	1	0	0	1	0 1 0	0 0 1									W L H
AXXX	1	0	1	0	0 1 0	0 0 1									W L H
BXXX	1	0	1	1	0 1 0	0 0 1									W L H
CXXX	1	1	0	0	0 1 0	0 0 1									W L H
DXXX	1	1	0	1	0 1 0	0 0 1									W L H
EXXX	1	1	1	0	0 1 0	0 0 1									W L H
FXXX	1	1	1	1	0 1 0	0 0 1									W L H
A5	A4	A3	A2	A1	A0	0	0	0	0	0	0	0	0	0	
						7	6	5	4	3	2	1	0		

L = LOW BYTE
H = HIGH BYTE

0 = ENABLE
1 = DISABLE

0 = NO SHORTING PLUG
X = SHORTING PLUG INSTALLED

16 BIT DATA BUS

INSTALL SHORTING PLUG AT JUMPER J20.

INSTALL SHORTING PLUGS
PER THE FOLLOWING TABLE:

DEVICE DENSITY = 4K BYTES

JUMPERS

1-4		5-8	
J21	J22	J23	J24
0	X	0	X
X	0	X	0

2K
4K/8K

X = HEX DIGITS

ADDRESS INPUTS
3628A

OUTPUTS

Figure 6. 2732 or 2732A

SYSTEM ADDRESS A0-15 HEX	DECODER CIRCUIT INPUTS						CE'S								BYTE
	BAF	BAE	BAD	BAC	BHEN	LA0	7	6	5	4	3	2	1	0	
0XXX	0	0	0	0	0 1 0 0	0 0 1							0 0 0	0 0 0	W L H
1XXX	0	0	0	1	0 1 0 0	0 0 1							0 0 0	0 0 0	W L H
2XXX	0	0	1	0	0 1 0 0	0 0 1							0 0 0	0 0 0	W L H
3XXX	0	0	1	1	0 1 0 0	0 0 1							0 0 0	0 0 0	W L H
4XXX	0	1	0	0	0 1 0 0	0 0 1					0 0 0				W L H
5XXX	0	1	0	1	0 1 0 0	0 0 1					0 0 0				W L H
6XXX	0	1	1	0	0 1 0 0	0 0 1					0 0 0				W L H
7XXX	0	1	1	1	0 1 0 0	0 0 1					0 0 0				W L H
8XXX	1	0	0	0	0 1 0 0	0 0 1			0 0 0						W L H
9XXX	1	0	0	1	0 1 0 0	0 0 1			0 0 0						W L H
AXXX	1	0	1	0	0 1 0 0	0 0 1			0 0 0						W L H
BXXX	1	0	1	1	0 1 0 0	0 0 1			0 0 0						W L H
CXXX	1	1	0	0	0 1 0 0	0 0 1	0 0 0	0 0 0							W L H
DXXX	1	1	0	1	0 1 0 0	0 0 1	0 0 0	0 0 0							W L H
EXXX	1	1	1	0	0 1 0 0	0 0 1	0 0 0	0 0 0							W L H
FXXX	1	1	1	1	0 1 0 0	0 0 1	0 0 0	0 0 0							W L H
X = HEX DIGITS	A5	A4	A3	A2	A1	A0	0 7	0 6	0 5	0 4	0 3	0 2	0 1	0 0	

L = LOW BYTE
H = HIGH BYTE
0 = ENABLE
1 = DISABLE
0 = NO SHORTING PLUG
X = SHORTING PLUG INSTALLED

16 BIT DATA BUS

INSTALL SHORTING PLUG AT JUMPER J20.

INSTALL SHORTING PLUGS PER THE FOLLOWING TABLE:

DEVICE DENSITY = 8K BYTES

JUMPERS				
1-4		5-8		
PROMS:				
	J21	J22	J23	J24
2K	0	X	0	X
4K/8K	X	0	X	0

Figure 7. 2764

Adjusting the V_{PP} Voltage Level

The high level of the V_{PP} pulse must be calibrated to 21V. The 8085A code sequence shown below or an equivalent write routine can be used to generate a series of V_{PP} pulses for initial calibration purposes.

```

MVI A,
COUNT      ; COUNT = number required for
              delay of at least 40 ms.

OUT 0        ; RESET the board

WRTLP:
STA 8000H    ; send a write command to the E2
              Memory board

LXI B, 0

DLYLP:
INX B
CMP B        ; compare B reg with Count
JNZ DLYLP    ; done yet?
OUT 0        ; Yes, RESET board and start again
JMP WRTLP

```

The oscilloscope used should first be calibrated against a known 21.0V DC source. For the above program

loop, the board address is 8000H and the RESET I/O address 00H. Remove the shorting plugs from J9-J12. Set switches SW 1-5 to on, off, off, on, on, respectively. Before running any V_{PP} pulse loop on the E² Board,

1. Remove all shorting plugs from jumpers J1-J8
2. Remove *all* 2816's from the board. Otherwise the maximum write cycle capacity at the addressed 2816 could be exceeded and the useful device life could be diminished.

XACK Delay

To select R7 use the following table and the tacc value of the slowest device in the PROM Array:

tacc (ns)	XACL delay (ns)	R7 (ohms)
200	250	6K
250	300	7.5K
350	400	12K
450	500	15K
650	700	24K

USER'S OPERATIONAL INSTRUCTIONS

The Multibus Board can be read by simply sending a Memory Read command to the board.

A byte or word write is performed on the system by doing a normal Memory Write Cycle. The Bus CPU will be informed approximately 25ms later via an Interrupt Line that the E² Board has completed the write operation. The CPU clears the Interrupt by RESETING the E² Board. The board is then ready for a new command.

Each 2816 E²PROM on the E² Board can be erased with one write operation. To accomplish this, the board is first put into Chip Erase Mode by doing an I/O Write cycle to the Chip Erase I/O address. The data written

during the I/O Write cycle is not used by the E² Board. A Memory Write cycle is then performed on the 2816 to be erased. As with the data write cycle described above, an Interrupt Line will be lowered when the Chip Erase operation has been completed. The CPU issues a RESET to the E² Board by doing an I/O Write cycle to the RESET I/O address. (The data put on the system bus during the RESET I/O write cycle is not used.) The 2816 that was written now contains all 1's, the Chip Erase Mode is cleared, and the E² Board is ready for the next command.

After powering up the E² Memory Board, the CPU must send an initial RESET to the E² Board to prepare it for normal operation. This should not occur until the CPU has been running for at least 1 second.

E² Memory Board Operation Summary

Operation	CPU Action	E ² Board Action	Comments
Read	Memory Read command MRDC	data requested is put on the bus	Minimum delay from MRDC to \overline{XACK} = 250 ns
Write	Memory Write command MWTC	an \overline{INT} line is pulled low when operation is done	byte or word erase and byte or word write is performed on 2816 or 2816 pair
	issue RESET		
Chip Erase	Set Chip Erase Mode with an I/O Write Command—then send an MWTC to the one or two 2816's to be erased	\overline{INT} goes low when done	One or two 2816's are set to all 1's
	issue RESET		
Initialize E ² Board	After the CPU starts running, wait 1 second, then send RESET command.		E ² Board is ready for operation

USER PROGRAM EXAMPLE

This sample program transfers a block of data from a RAM buffer to the E² memory on the E² Memory Board. The system data bus is 8-bits wide, and the RAM memory block is located from 0 to 64K. (The Memory Board is located from 8000H to BFFFH. The system RAM is inhibited by $\overline{INH1}$ from the E² Board whenever the latter is accessed.) All 8 MOS PROM sockets are loaded with 2816's. The I/O addresses are 00H for RESET and 01H for Chip Erase Mode. The data transfer in this example consists of less than 4K bytes. The transfer is started by doing an initial Memory Write Cycle to the E² Board. Following the Write Cycle, the

interrupt subroutine (SRVINT) RESET's the E² Board after each write operation has been completed. The subroutine will then take the next data byte from the RAM source block and write it to the next E² location. At this point, the subroutine returns control to the main program which in this example idles in a tight loop. An actual system CPU would continue doing its main processing until the present write operation was done. Once the data transfer is started, the interrupt subroutine will take care of resetting the E² Board and writing the next byte. The subroutine takes only about 100 μ s out of every 20 ms of CPU time to carry out the data transfer. The data transfer is thus highly efficient.

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LOC	OBJ	LINE	SOURCE STATEMENT
		1 ;	
		2 ;	
		3 ;	*****
		4 ;	
		5 ;	
		6 ;	INTEL CORPORATION
		7 ;	
		8 ;	SPD E2 MULTIBUS COMPATIBLE MEMORY BOARD
		9 ;	
		10 ;	APPLICATION PROGRAM
		11 ;	
		12 ;	
		13 ;	
		14 ;	
		15 ;	*****
		16 ;	
		17 ;	
		18 ;	
		19 ;	
		20 ;	THIS PROGRAM DOES A DATA TRANSFER
		21 ;	BETWEEN A BLOCK OF RAM AND THE E2
		22 ;	MEMORY BOARD
		23 ;	
		24 ;	THE RAM BLOCK IS LOCATED AT 0C000H
		25 ;	
		26 ;	THE E2 BOARD IS LOCATED AT ADDRESS 8000H
		27 ;	
		28 ;	IO ADDRESSES:
		29 ;	00H - RESET
		30 ;	01H - CHIP ERASE
		31 ;	
		32 ;	INTERRUPT LINE 7 (INT7) IS USED TO INFORM
		33 ;	THE CPU WHEN THE E2 BOARD HAS COMPLETED A
		34 ;	BYTE ERASE/WRITE OR A CHIP ERASE COMMAND
		35 ;	
		36 ;	0E00H DATA BYTES ARE TRANSFERRED
		37 ;	
		38 ;	
		39 ;	
		40 ;	
		41 ;	
8000		42	STRADD EQU 8000H
00FC		43	INTMSK EQU 0FCH
00FD		44	OLRSTR EQU 0FDH
0000		45	CR EQU 0DH
000A		46	LF EQU 0AH
0009		47	EXIT EQU 9
		48 ;	
		49	EXTRN CD, CI, ISIS
		50 ;	
		51 ;	
		52 ;	
7800		53	ORG 7800H
		54 ;	

LOC	OBJ	LINE	SOURCE STATEMENT
7800	C34678	55	JMP INIT
		56 ;	
		57 ;	
		58 ;	
		59 ;	*****
		60 ;	
		61 ;	
		62 ;	
		63 ;	DATA STRINGS
		64 ;	
		65 ;	
		66 ;	*****
		67 ;	
		68 ;	
7803	5452414E	69	TRMSG: DB 'TRANSFER IN PROGRESS', CR, LF, 0FFH
7807	53464552		
7808	20494E20		
780F	50524F47		
7813	52455353		
7817	00		
7818	0A		
7819	FF		
781A	44415441	70	ERRMSG: DB 'DATA ERROR', CR, LF, 0FFH
781E	20455252		
7822	4F52		
7824	00		
7825	0A		
7826	FF		
7827	5452414E	71	FINMSG: DB 'TRANSFER COMPLETE', CR, LF, 0FFH
782B	53464552		
782F	20434F40		
7833	504C4554		
7837	45		
7838	00		
7839	0A		
783A	FF		
783B	3D78	72	EBLK: DW ESTAT
		73 ;	
		74 ;	
		75 ;	
		76 ;	*****
		77 ;	
		78 ;	
		79 ;	TEMPORARY STORAGE SPACE
		80 ;	
		81 ;	
		82 ;	*****
		83 ;	
		84 ;	
783D		85	ESTAT: DS 2
783F		86	E2BUSY: DS 1
7840		87	MSGADD: DS 2
7842		88	SRCADD: DS 2
7844		89	DESADD: DS 2
		90 ;	

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LOC	OBJ	LINE	SOURCE STATEMENT
		91 ;	
		92 ;	
		93 ;	
		94 INIT:	
7846	31007E	95	LXI SP, 7E00H
7849	D300	96	OUT 0 ; RESET THE E2 BOARD
		97 ;	
		98 ;	
		99 ;	LOAD LOCATION 038H (INTERRUPT 7 VECTOR)
		100 ;	WITH JUMP TO SERVICE INTERRUPT SUBROUTINE
		101 ;	
784B	3EC3	102	MVI A, 0C3H
784D	323000	103	STA 30H
7850	21AE78	104	LXI H, SRVINT
7853	223900	105	SHLD 39H
		106 ;	
		107 ;	SET THE SYSTEM INTERRUPT MASK TO
		108 ;	ENABLE INTERRUPTS 1 AND 7
		109 ;	
		110 ;	
		111 ;	
7856	3E7E	112	MVI A, 7EH
7858	D3FC	113	OUT INTMSK
785A	FB	114	EI
785B	210378	115	LXI H, TRMSG ; INFORM OPERATOR
		116	; THAT THE TRANSFER
		117	; HAS BEGUN
		118 ;	
785E	224078	119	SHLD MSGADD
7861	CDE578	120	CALL DISMSG
		121 ;	
		122 ;	
		123 ;	
		124 ;	*****
		125 ;	
		126 ;	MAIN PROGRAM
		127 ;	
		128 ;	
		129	MAINPG:
		130 ;	
		131 ;	LOAD SOURCE RAM BLOCK WITH 55H
		132 ;	
7864	2100C0	133	LXI H, RAMBLK
		134	LDLP:
7867	3655	135	MVI M, 55H
7869	23	136	INX H
786A	3ECE	137	MVI A, 0CEH
786C	BC	138	CMP H
786D	C26778	139	JNZ LDLP
		140 ;	
		141 ;	
7870	3EFF	142	MVI A, 0FFH
7872	77	143	MOV M, A ; INSERT END OF DATA STRING
		144	;
		145 ;	MARKER

LOC	OBJ	LINE	SOURCE STATEMENT
		146 ;	
		147 ;	INITIATE DATA TRANSFER
		148 ;	
		149 ;	
7873	210080	150	LXI H,STRADD
7876	224478	151	SHLD DESADD ;STORE STARTING ADDRESS OF
		152	;E2 BOARD
7879	2100C0	153	LXI H,RAMBLK
787C	224278	154	SHLD SRCADD ;STORE STARTING ADDRESS OF
		155	;SOURCE RAM BLOCK
787F	7E	156	MOV A,M ;FETCH FIRST BYTE FROM SOURCE
7880	2A4478	157	LHLD DESADD ;LOAD DESTINATION ADDRESS
		158	; (E2 BOARD)
		159 ;	
		160	STXFER:
7883	77	161	MOV M,A ;WRITE FIRST BYTE TO E2
		162	;BOARD
7884	3E01	163	MVI A,1
7886	323F78	164	STA E2BUSY ;SET FLAG INDICATING THAT A
		165	;DATA TRANSFER IS IN PROGRESS
		166 ;	
		167 ;	
		168 ;	
		169 ;	
		170 ;	THIS TIGHT LOOP SIMULATES AN ACTUAL SYSTEM CPU
		171 ;	DOING ITS MAIN PROCESSING
		172 ;	
		173 ;	
		174	PROCES:
7889	3A3F78	175	LDA E2BUSY
788C	FE01	176	CPI 1
788E	CA8978	177	JZ PROCES
		178 ;	
		179 ;	
		180 ;	
		181 ;	ONCE THE DATA TRANSFER IS COMPLETED THE OPERATOR
		182 ;	IS INFORMED AND CONTROL IS RETURNED TO ISIS
		183 ;	
		184 ;	
		185 ;	
		186 ;	
		187	FINISH:
7891	212778	188	LXI H,FINMSG
7894	224878	189	SHLD MSGADD
7897	CDE578	190	CALL DISMSG
		191 ;	
		192 ;	
		193 ;	
		194	RTISIS:
789A	0E09	195	MVI C,EXIT
789C	113B78	196	LXI D,EBLK
789F	CD0000	197	CALL ISIS
		198 ;	
		199 ;	
		200 ;	

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LOC	OBJ	LINE	SOURCE STATEMENT	THRU	TO	DATE	TIME
		201	ERROR:				
78A2	211A78	202	LXI H,ERRMSG				
78A5	224078	203	SHLD MSGADD				
78A8	CDE578	204	CALL DISMSG				
78AB	C39A78	205	JMP RTISIS				
		206 ;					
		207 ;					
		208 ;					
		209 ;*****					
		210 ;					
		211 ;					
		212 ;	SUBROUTINES				
		213 ;					
		214 ;					
		215 ;					
		216 ;					
		217 ;					
		218 ;	WHEN THE E2 BOARD HAS COMPLETED ITS BYTE				
		219 ;	ERASE/WRITE CYCLE THIS ROUTINE WILL VERIFY				
		220 ;	THE WRITTEN DATA. THE NEXT BYTE IS FETCHED				
		221 ;	FROM THE RAM BLOCK AND WRITTEN TO THE NEXT				
		222 ;	LOCATION ON THE E2 BOARD.				
		223 ;					
		224 ;					
		225 ;					
		226 ;					
		227	SRVINT:				
78AE	FB	228	EI				
		229 ;					
		230 ;	SAVE ALL REG'S				
		231 ;					
78AF	F5	232	PUSH PSM				
78B0	C5	233	PUSH B				
78B1	D5	234	PUSH D				
78B2	E5	235	PUSH H				
78B3	D300	236	OUT 0 ;RESET THE E2 BOARD				
		237 ;					
78B5	2A4478	238	LHLD DESADD				
78B8	7E	239	MOV A,M				
78B9	2A4278	240	LHLD SRCADD				
78BC	BE	241	CMP M ;CORRECT DATA?				
78BD	C2A278	242	JNZ ERROR				
		243 ;					
		244 ;	YES, CONTINUE				
		245 ;					
78C0	23	246	INX H				
78C1	7E	247	MOV A,M				
78C2	FEFF	248	CPI 0FFH ;END OF STRING MARKER?				
78C4	CAD578	249	JZ DONE				
		250 ;					
		251 ;	NO, CONTINUE				
		252 ;					
78C7	224278	253	SHLD SRCADD				
78CA	2A4478	254	LHLD DESADD				
78CD	23	255	INX H				

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LOC	OBJ	LINE	SOURCE STATEMENT	REGISTER INDEX	VAL	TYPE	VAL
78CE	77	256	MOV M, A ;WRITE NEW BYTE TO E2 BOARD		000	DATA	
78CF	224478	257	SHLD DESADD		000	DATA	
78D2	C3DA78	258	JMP REST ;RESTORE REG'S AND RETURN		000	DATA	
		259 ;			000	DATA	
		260 ;	CLEAR FLAG TO INFORM CPU THAT THE DATA TRANSFER		000	DATA	
		261 ;	IS FINISHED		000	DATA	
		262 ;			000	DATA	
		263 DONE:			000	DATA	
78D5	3E00	264	MVI A, 0		000	DATA	
78D7	323F78	265	STA E2BUSY		000	DATA	
		266 ;			000	DATA	
		267 REST:			000	DATA	
78DA	E1	268	POP H		000	DATA	
78DB	D1	269	POP D		000	DATA	
78DC	C1	270	POP B		000	DATA	
78DD	F3	271	DI		000	DATA	
78DE	3E20	272	MVI A, 20H		000	DATA	
78E0	D3FD	273	OUT OLRSTR		000	DATA	
78E2	F1	274	POP PSW		000	DATA	
78E3	FB	275	EI		000	DATA	
78E4	C9	276	RET		000	DATA	
		277 ;			000	DATA	
		278 ;			000	DATA	
		279 ;			000	DATA	
		280 ;			000	DATA	
		281 ;			000	DATA	
		282 ;			000	DATA	
		283 DISMSG:			000	DATA	
78E5	2A4078	284	LHLD MSGADD		000	DATA	
		285 MSGLP:			000	DATA	
78E8	4E	286	MOV C, M		000	DATA	
78E9	3EFF	287	MVI A, 0FFH		000	DATA	
78EB	BE	288	CMP M		000	DATA	
78EC	C8	289	RZ		000	DATA	
78ED	CD0000	290	CALL CO		000	DATA	
78F0	23	291	INX H		000	DATA	
78F1	C3E878	292	JMP MSGLP		000	DATA	
		293 ;			000	DATA	
		294 ;			000	DATA	
		295 ;			000	DATA	
		296 ;	RAM BLOCK		000	DATA	
C000		297	ORG 0C000H		000	DATA	
C000		298	RAMBLK: DS 1000H		000	DATA	
		299 ;			000	DATA	
		300 ;			000	DATA	
		301 ;			000	DATA	
		302 ;			000	DATA	
7846		303	END INIT		000	DATA	
PUBLIC SYMBOLS							
EXTERNAL SYMBOLS							
CI	E 0000	CO	E 0000	ISIS	E 0000		

USER SYMBOLS

CI	E 0000	CO	E 0000	CR	A 0000	DESADD	A 7844	DISMSG	A 78E5	DONE	A 78D5	E2BUSY	A 783F
EBLK	A 783B	ERRMSG	A 781A	ERROR	A 78A2	ESTAT	A 783D	EXIT	A 0009	FINISH	A 7891	FINMSG	A 7827
INIT	A 7846	INTMSK	A 00FC	ISIS	E 0000	LDLP	A 7867	LF	A 000A	MAINPG	A 7864	MSGADD	A 7840
MSGLP	A 78E8	OLRSTR	A 00FD	PROCES	A 7889	RANBLK	A C000	REST	A 78DA	RTISIS	A 789A	SRCADD	A 7842
SRVINT	A 78AE	STRADD	A 8000	STXFER	A 7883	TRNMSG	A 7803						

ASSEMBLY COMPLETE, NO ERRORS

16-BIT DATA BUS STRUCTURE

The Multibus card can use either an 8-bit or 16-bit data bus. The PROM Array is organized in pairs of 8-bit wide MOS PROM's to enable the formation of a 16-bit word. For a 16-bit data bus, the upper byte MOS PROM is enabled whenever BHE (Byte High Enable) is low. The lower byte PROM is enabled when A0 is low. The upper and lower PROM's can be enabled and accessed separately as individual bytes or together to form a word. Accessing data by words takes half the time required to do byte operations; thus the advantage of 16-bit systems over 8-bit systems.

HARDWARE DESCRIPTION

Overview

This discussion assumes an 8-bit data bus is being used and applies equally to a 16-bit-wide system except that whenever a byte-wide operation is being described, two bytes (two MOS PROMs) in parallel are being affected.

The E² Board hardware consists of the following sections:

1. Sequencing and Timing
2. $\overline{\text{XACK}}$ Generation
3. Bus Address Decoding
4. PROM Array Decoding
5. Data and Address Latches and Buffers
6. V_{PP} and $\overline{\text{OE}}$ Drivers
7. 5V to 24V Converter
8. Write Protection Circuitry

See the block diagram in Figure 8.

A brief description of the function of each circuit block will be given. The circuit operation will then be discussed in detail in the subsections to follow.

The Sequencing and Timing circuitry generates the signals necessary to do the byte erase, byte write, chip erase cycles, and read cycles on the E² PROMs.

The $\overline{\text{XACK}}$ Generator returns the Transfer Acknowledge signal to the Multibus Bus Master after receiving any memory or I/O command.

The bus Address Decoder performs 2 functions:

1. Enabling the E² Board within its assigned address block for memory operations.
2. Enabling the RESET function and setting the Chip Erase Mode whenever the proper I/O addresses are written to.

The PROM Array Decoder enables the proper MOS PROM for any given memory address.

The Address and Data Latches hold the Bus address and data values for the duration of the E² write and Chip Erase operations. During read operations, the Data Buffers transfer the accessed data to the Multibus.

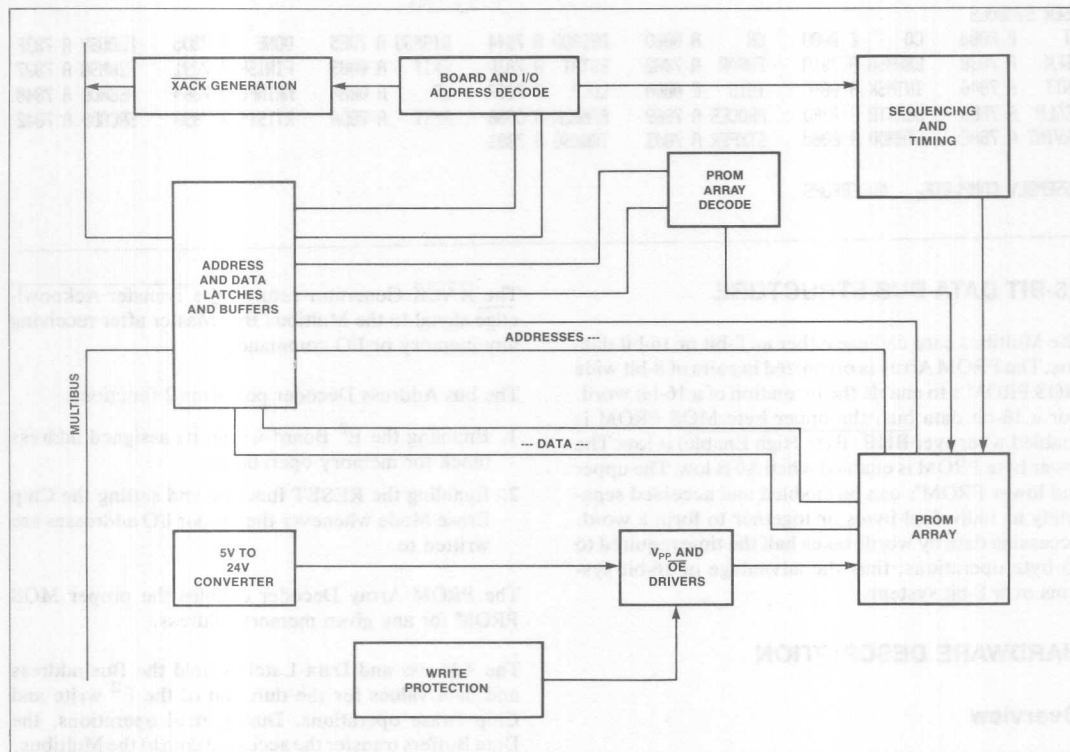
The V_{PP} and $\overline{\text{OE}}$ Drivers provide the high voltage pulses required for the byte erase, byte write, and Chip Erase cycles while the 5V to 24V Converters provide the supply voltage for the V_{PP} and $\overline{\text{OE}}$ drivers. Tied to these circuits is the Write Protection Circuitry which prevents any spurious write cycles from occurring during the system power up and power down transitions.

The figures referenced in the following subsections are shown in the Schematic Section.

Sequencing and Timing

READ OPERATION

When MRDC goes low the RDEN signal also goes low. WR Mode is normally high when the E² Board is not being accessed and is not performing an operation. WR Mode also stays high during a Read operation. The address latches in Figure 12 remain transparent, and lines BAC-BAF select one of the MOS PROMs in the PROM Array via the 3628A Bipolar PROM decoder. In Figure 13 the RDEN signal enables the 8287 transceivers to gate the output data onto the multibus. RDEN also causes $\overline{\text{OE}}$ to go low to read the data out of the MOS PROMs.

Figure 8. E² Board Block Diagram

WRITE OPERATION

Refer to Figures 10 and 11 and to the timing diagram in Figure 9.

When $\overline{\text{MWT}}\overline{\text{C}}$ goes low the $\overline{\text{BDWR}}$ signal also goes low which sets the WR Mode FF. The falling edge of $\overline{\text{WR}}$ Mode latches the addresses as the falling edge of $\overline{\text{BD}}$ $\overline{\text{WR}}$ latches the data. The rising edge of $\overline{\text{BDWR}}$ sets the Start Erase Cycle FF, which in turn starts the one-shot chain.

The first one-shot delays the rising edge of V_{pp} to provide some set-up time for CE. When the delay one-shot times out, it triggers the V_{pp} ON one-shot. This second one-shot turns on the V_{pp} driver for approximately 10ms. This is the byte erase cycle. Although the bus data has been latched, the latch outputs are not yet enabled by Data In En (Figure 13). The 1K pullup resistors on the LD0-LD15 lines pull the high-impedance latch outputs up to 5V. As a result, the data inputs to the E²PROM are all 1's which in turn erase the addressed data byte. When the V_{pp} ON one-shot times out, the V_{pp} Discharge one-shot is triggered. The V_{pp} driver is

now shut off ($\overline{V_{\text{pp}}\text{ ON}} = 1$) but the voltage on the V_{pp} line will take a long time to discharge to 5V. This is due to the 4.7 μf of low-frequency decoupling capacitor, connected from V_{pp} to ground; the capacitor is needed to suppress low frequency noise (See Figure 17). In order to pull the V_{pp} line down fast, the V_{pp} Discharge signal turns on Q8 which discharges the capacitor. When the third one-shot times out, the Cycle Done One-Shot starts, which clears the start Erase Cycle FF and forces $\overline{\text{CE}}$ high (Figure 16 and Figure 10). The rising edge of Cycle Done sets the Start Write Cycle FF and causes the 74LS393 counter (Figure 10) to increment from 0 to 1. This starts the one-shot chain again to perform the byte write cycle. The Data In En signal enables the latched data onto the input lines. The one-shot chain then delays, activates V_{pp} , and discharges the V_{pp} line. This time the data byte is written into the selected 2816 address location. The 74LS393 counter is incremented a second time and its QB output lowers one of the Multibus Interrupt Lines. The CPU RESETS the E² board with an IOWC command. The WR Mode FF, the Start Write FF and the 74LS393 counter are cleared, and the E² Board is ready for the next operation.

CHIP ERASE OPERATION

The Chip Erase Operation is quite similar to the byte erase operation. The differences are:

1. The Chip Erase FF is set by the Multibus CPU before initiating the write operation. The Chip Erase FF is set by doing an $\overline{\text{IOWC}}$ command to the Chip Erase address.
2. When the write operation begins, the $\overline{\text{OE}}$ signal is raised to 14.5V (Figure 17). The byte erase cycle proceeds as before.
3. At the end of the byte erase cycle the Cycle Done signal does not set the Start Write Cycle FF. Instead, the Start Write Cycle FF is held in a clear state by the $\overline{\text{INH}}$ Byte Write signal shown in Figure 10. Cycle Done increments the 74LS393 counter from 0 to 1. The Q_A output is now used to lower one of the Interrupt Lines to signal the CPU that the Chip Erase Operation is complete. When the CPU resets the E^2 Board, the Chip Erase FF is also cleared.

INITIALIZATION

The E^2 Board must be RESET after power up. Due to the write protection circuitry delay period after power up, the RESET should not be sent until at least 1 second after the CPU starts running. Once the board is RESET, it is ready for a command.

XACK Generation

(Figure 11) The $\overline{\text{XACK}}$ (Transfer Acknowledge) signal is driven low after a delay period determined by the t_{ACC} of the slowest MOS PROM in the PROM Array. $\overline{\text{XACK}}$ stays low until the Memory or I/O command goes back high. See the XACK delay subsection.

Bus Address Decoding

Two sets of addresses need to be decoded for the E^2 Memory Board: the memory space address for the PROM Array and the I/O address for Chip Erase Mode and the RESET function. The 74LS85 comparators in Figure 16, along with Jumpers J9–J12 and J13–J19, are used to select the desired addresses and generate the appropriate enabling signals when the selected addresses appear on the Multibus. The board memory address is determined by jumpers J9–J12. When the correct memory address is put on the bus, the $\overline{\text{MEM}}$ EN signal goes low. The $\overline{\text{INH1}}$ (INHIBIT RAM) signal is driven low on the Multibus to disable any RAM memory that is occupying the same memory space as the E^2 Board.

When the selected I/O address appears on the system bus and $\overline{\text{IOWC}}$ goes low the $\overline{\text{BD IOW}}$ signal goes low

(Figure 16). If ADR0 is low, the RESET function is activated. If ADR0 is high, the Chip Erase FF is set.

MOS PROM Array Decoder

(Figure 12) Details on how to program the 3628A Bipolar PROM decoder are given in the Installation Instructions under PROM Array Decoder. The 3628A acts as a sophisticated decoder. The address input to the 3628A allows a maximum address range of 64K with a minimum resolution of 2K. The A0 and $\overline{\text{BHEN}}$ input signals enable the 3628A to select the lower byte MOS PROM, the upper byte MOS PROM, or both in parallel. The 3628A output lines connect to an 8282 8-bit latch. The 8282 latches the decoder output to provide $\overline{\text{CE}}$ for the 10ms erase and write cycles. During read cycles the 8282 simply acts as a buffer for the decoder.

Address and Data Latches and Buffers

The 8283s and 8282 of Figures 12 and 13 latch the address and data from the Multibus when the CPU issues an $\overline{\text{MWTc}}$ command. These address and data values stay latched throughout the Write Operation. The addresses are latched on the falling edge of $\overline{\text{WR}}$ Mode. The input data from the bus is latched by the falling edge of $\overline{\text{WR EN}}$ (See Figure 13). For Read operations the $\overline{\text{WR}}$ Mode signal stays high. A high on the 8283 STB input puts these latches in "transparent" mode: they act as buffers for the bus addresses. The 8287s in Figure 13 act as data output buffers for the accessed MOS PROM data.

The 8286 is used when the system data bus is 8-bits wide. This transceiver transfers the data byte from the LD0-LD7 low byte data bus to LD8-LD15 upper byte data bus for write operations. For read operations, the data byte from the LD8-LD15 byte bus is transferred to the LD0-LD7 data byte bus. This byte swapping circuit is actually adapting the 16-bit upper/lower byte structure to an external 8-bit wide data bus. See the section on 16-bit Data Bus Structure for more information.

V_{PP} and $\overline{\text{OE}}$ Drivers

Refer to Figure 17. The V_{PP} driver provides the 21V V_{PP} programming pulse for the 2816. The pulse goes from 5V to 21V with an exponential rising edge. The $\overline{\text{OE}}$ driver is used to provide nominal TTL levels for read and write operations. This driver also provides a 14.5V level for the Chip Erase cycle.

5V to 24V Converter

Refer to Applications Note AP-103 in the E^2 PROM Applications Handbook. (Also Figure 18.)

Write Protection Circuitry

The Write Protection circuits are designed to prevent the TTL control logic from causing an E² write/erase cycle to occur during the periods of board power up or power down. The 747 op-amp in Figure 18 senses when the board 5V supply has dropped below the voltage level on C41. When this happens, the op-amp disables the V_{PP} driver by grounding C38 (Figure 17). This prevents the capacitor from charging up the 21V—it is the exponential rising voltage on this capacitor which is used to generate the V_{PP} programming pulse's rising edge.

When the E² Board is powered up, the rising V_{CC} voltage begins charging up capacitor C30. Until the voltage on C30 is high enough to turn on Q4 (approximately 3.5V), this transistor will hold the V_{PP} OFF signal low. This is the same signal in Figures 18 and 17 that is used by the power-down circuit described

above. This keeps the V_{PP} driver disabled until about 500ms after V_{CC} reaches 5V. About 400ms before V_{CC} reaches 5V, the Write Protect FF in Figure 10 is set by the Multibus INIT signal. This FF will hold the V_{PP} ON one-shot disabled until the CPU RESETS the E² Memory Board and the Write Protect FF. Thus, the Q4/C30 circuit holds the V_{PP} driver off until long after the TTL logic has stabilized and the Write Protect FF has disabled the V_{PP} ON one-shot.

The purpose of the Write Protect Flip Flop is to prevent the 2816s from being written to by the Intellec Monitor Program immediately after power up. The Intellec Monitor tries to write to every location in its addressable range after power up. This is done to determine how much RAM is in the system. In a non-Intellec system the INIT signal is not really needed as long as no System Write commands occur other than those generated by the user.

SCHEMATIC DIAGRAMS

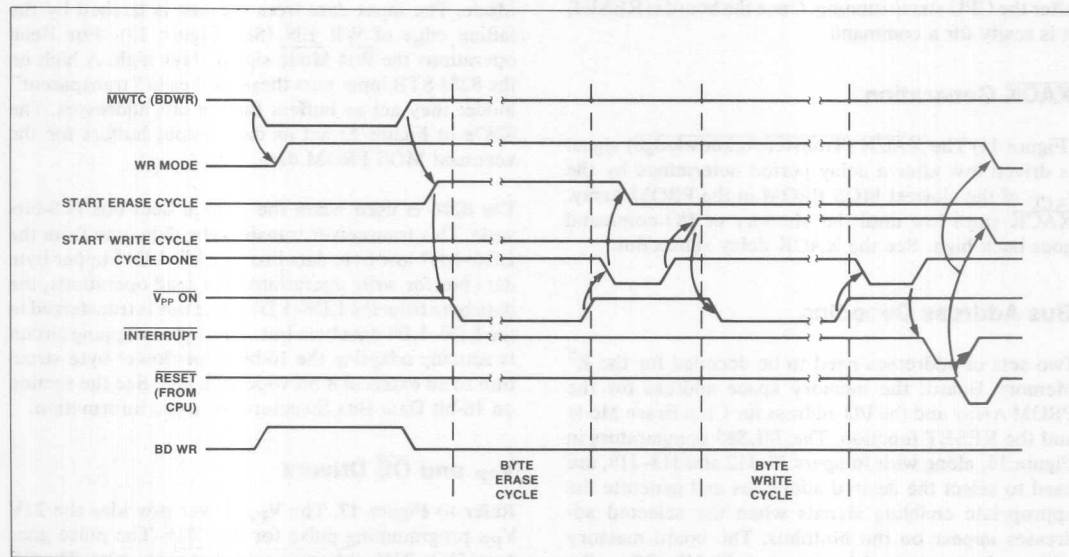


Figure 9. Write Operation: Byte Erase and Byte Write Cycles

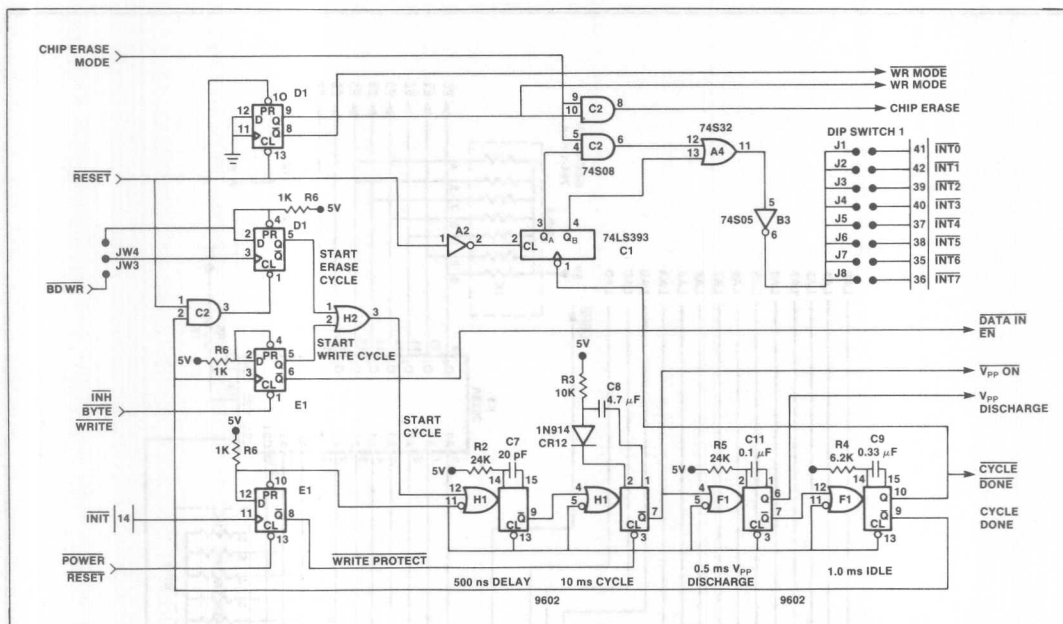


Figure 10. Write and Erase Sequencing and Timing

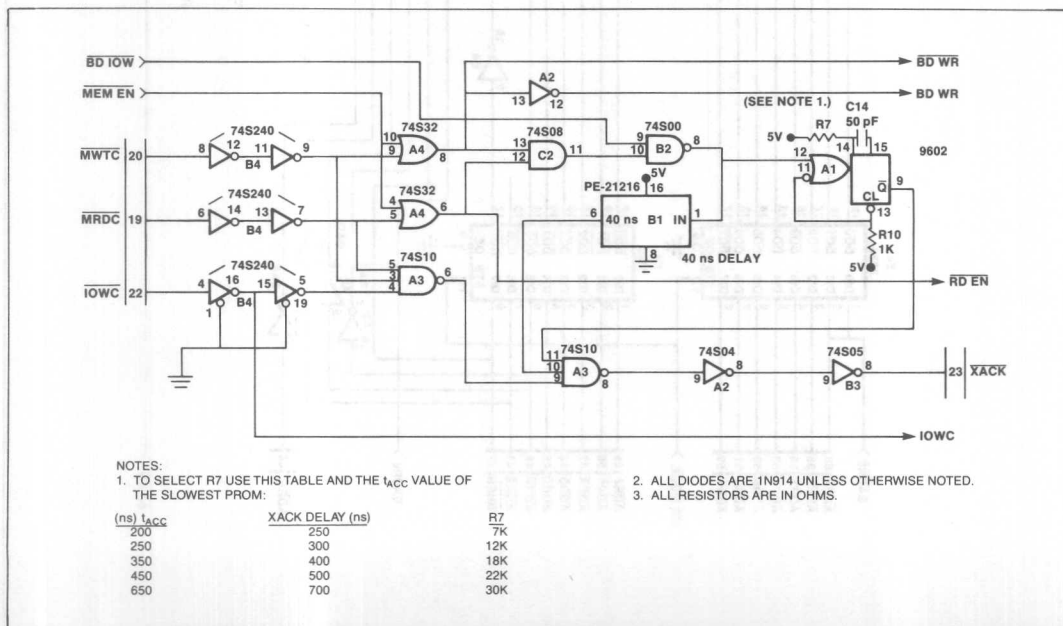


Figure 11. XACK Generator

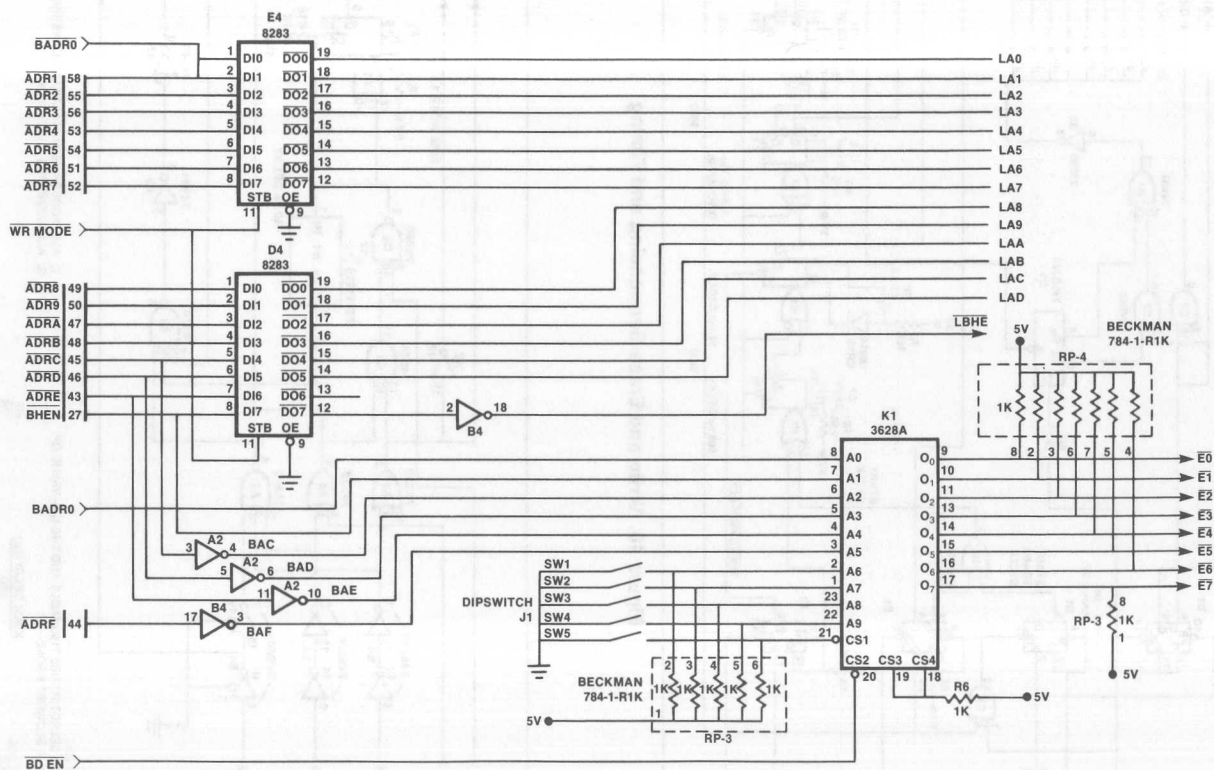
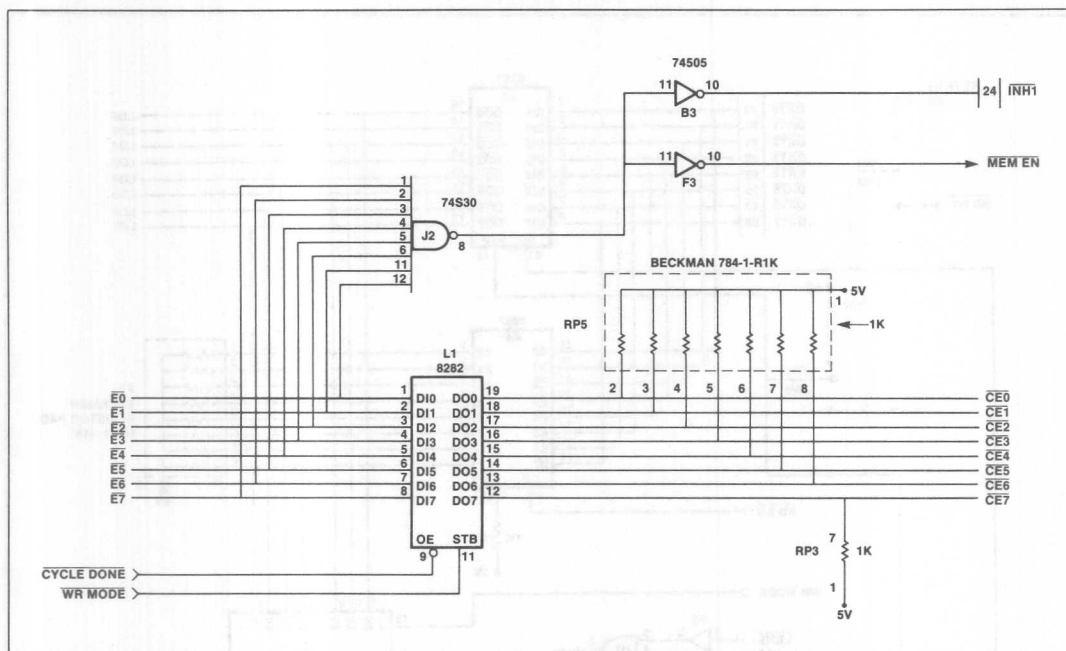


Figure 12. Address Latches and MOS PROM Array Decoder



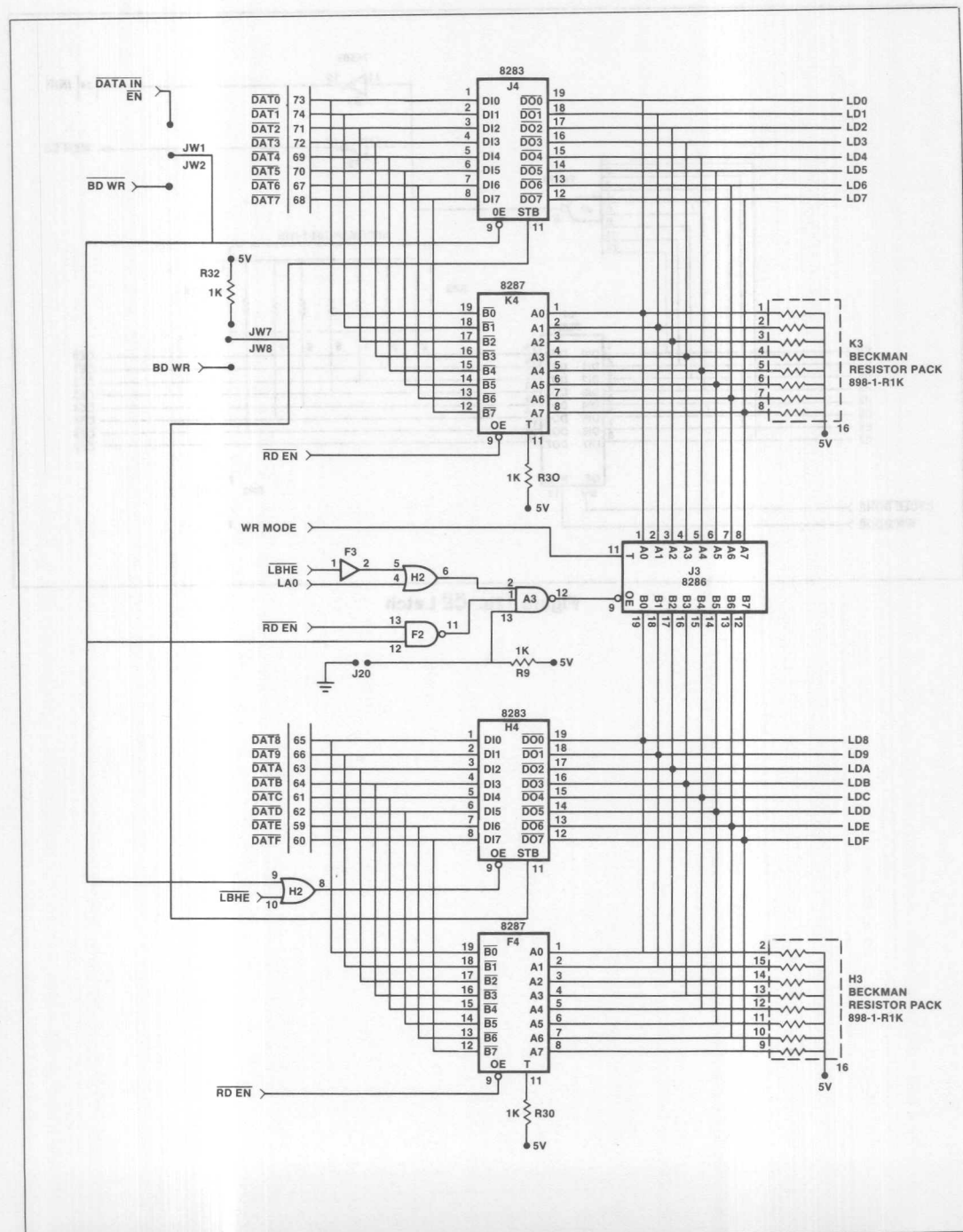


Figure 13. Data In Latch, Data Out Buffer, and Upper/Lower Byte Transceiver

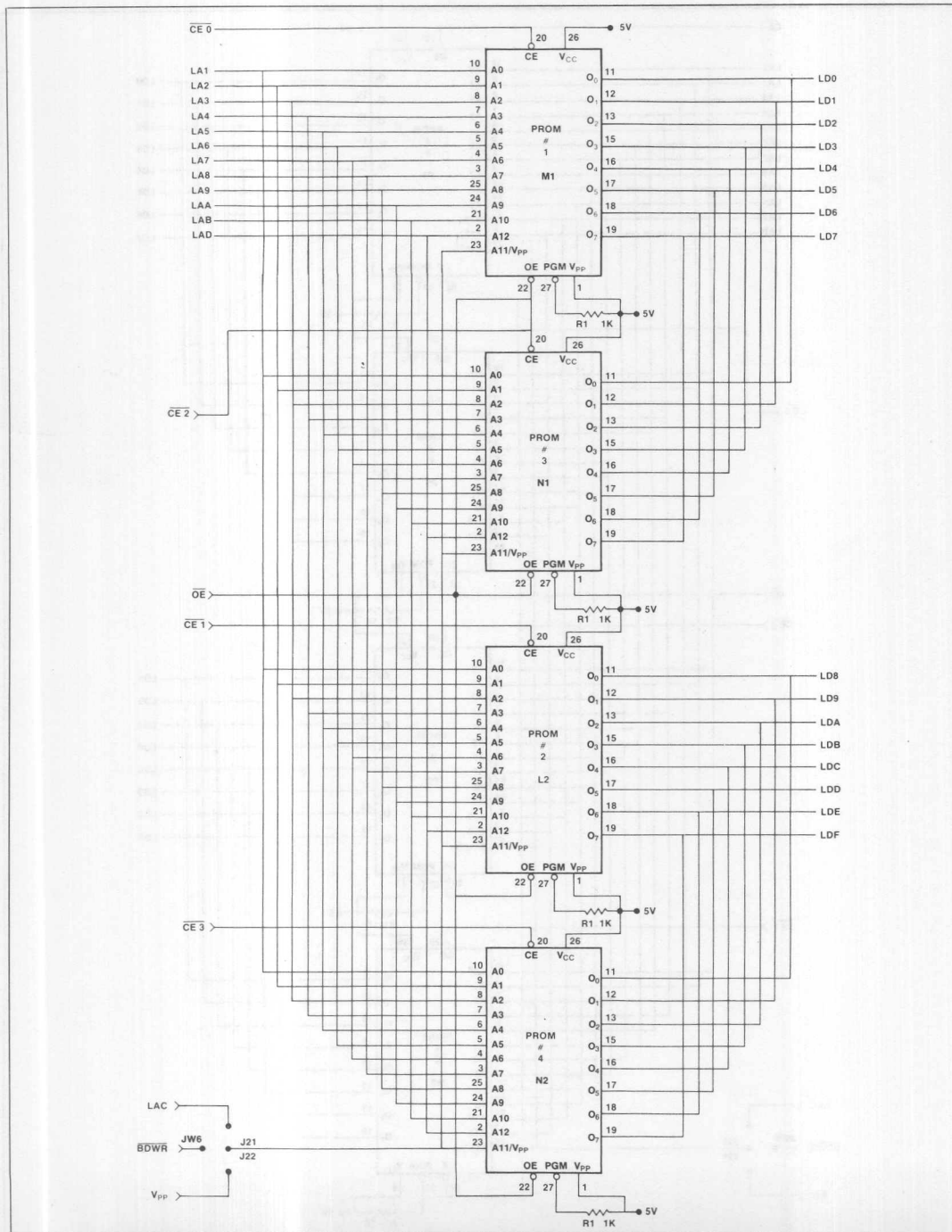


Figure 14. MOS PROM Array

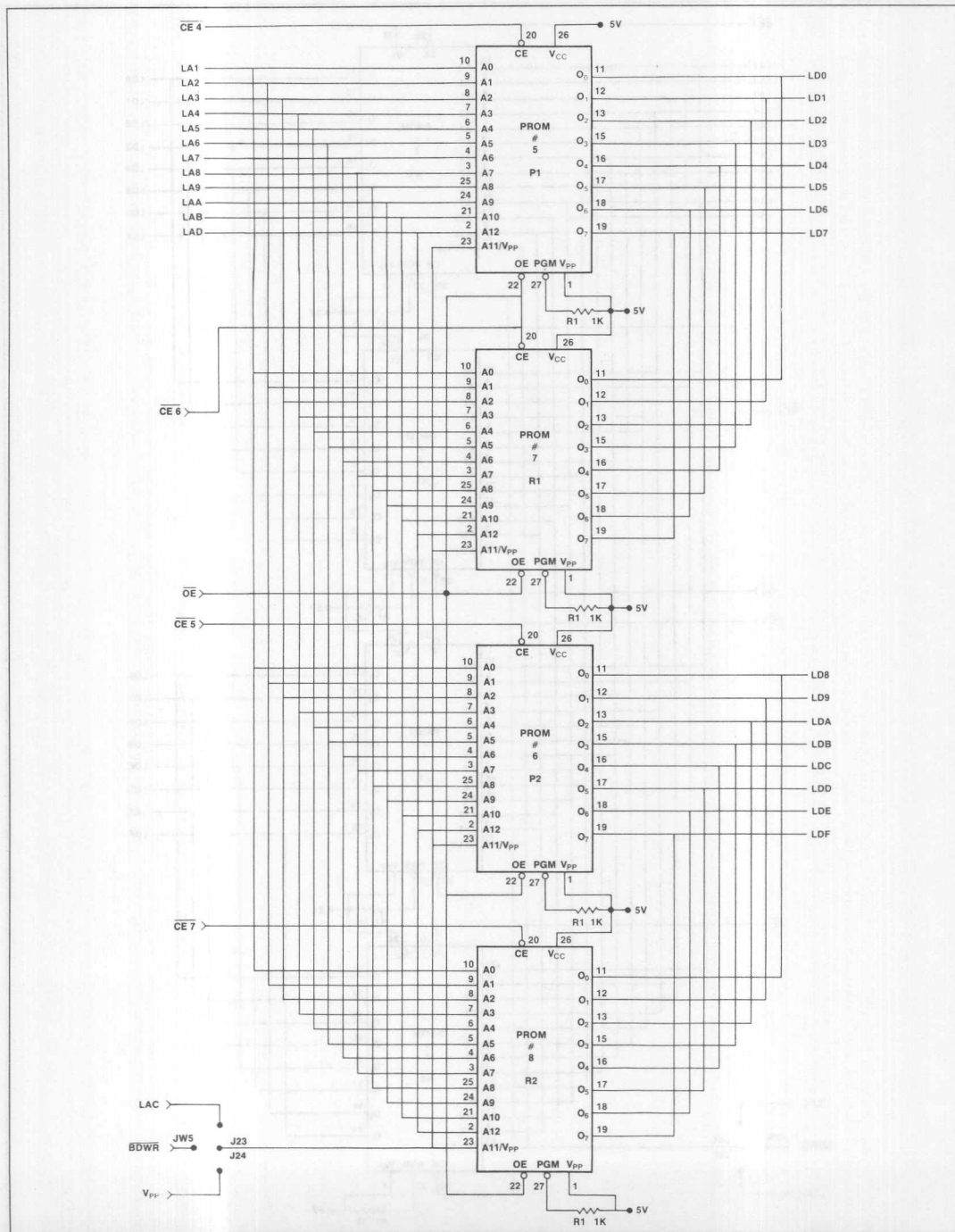


Figure 15. MOS PROM Array

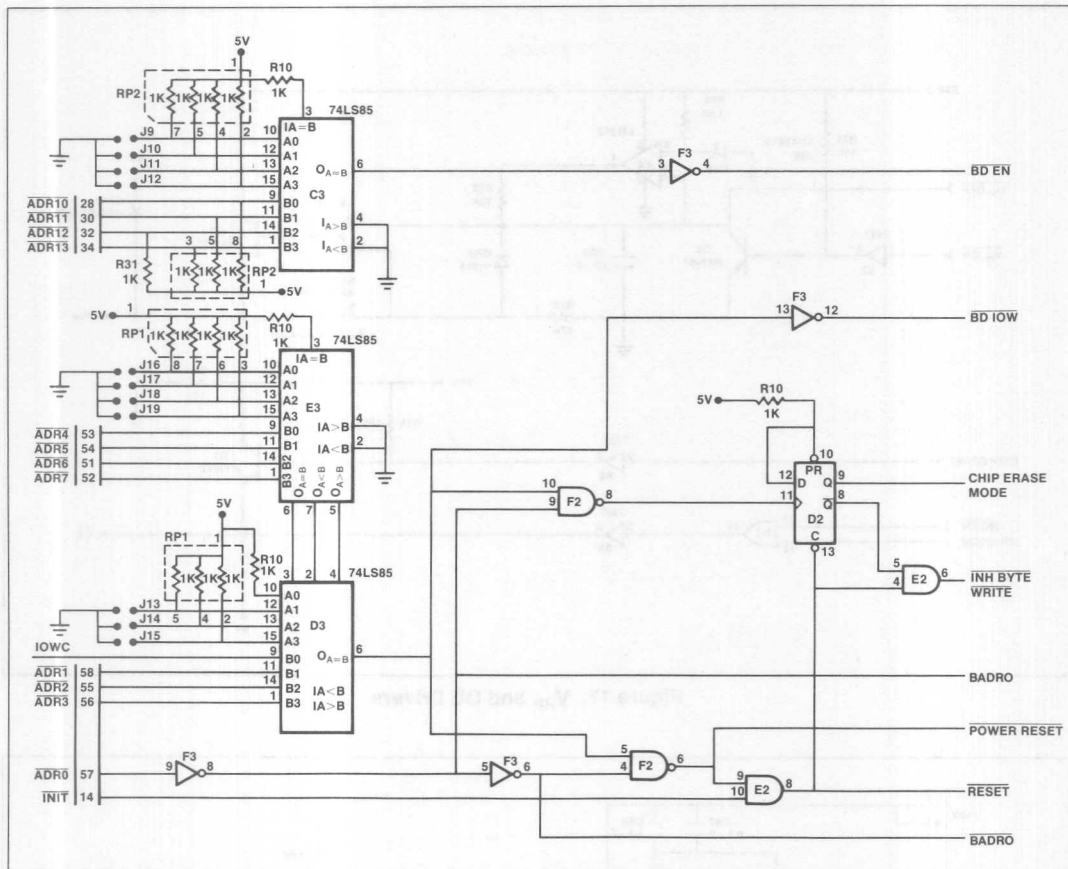


Figure 16. Board Address Location Selection, RESET and Chip Eraser I/O Address Selection

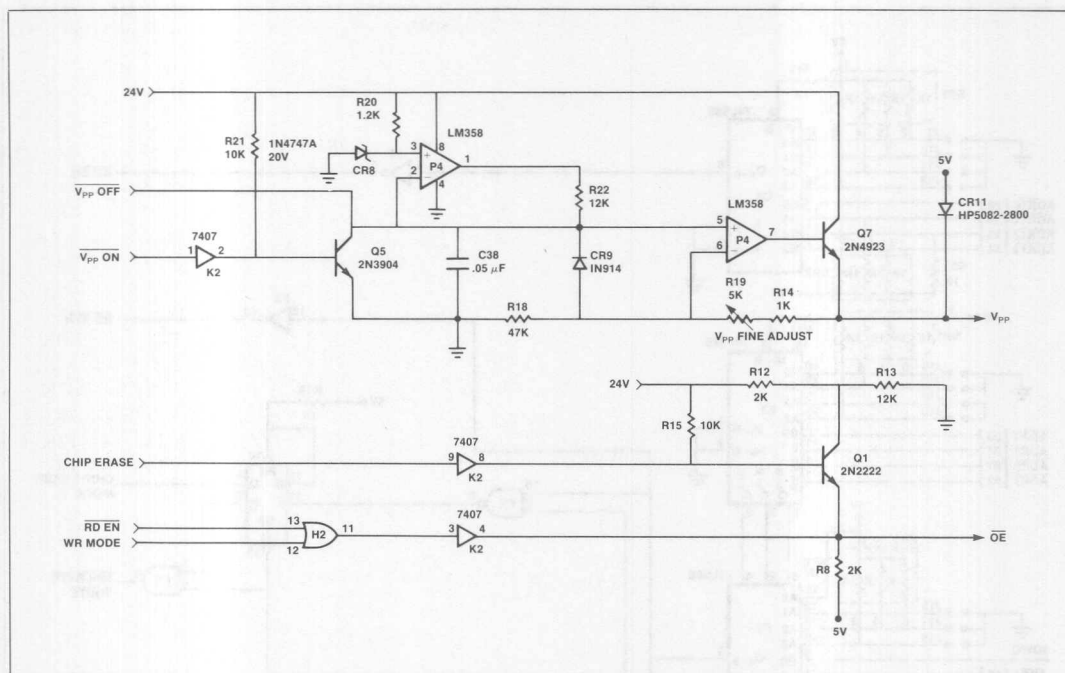
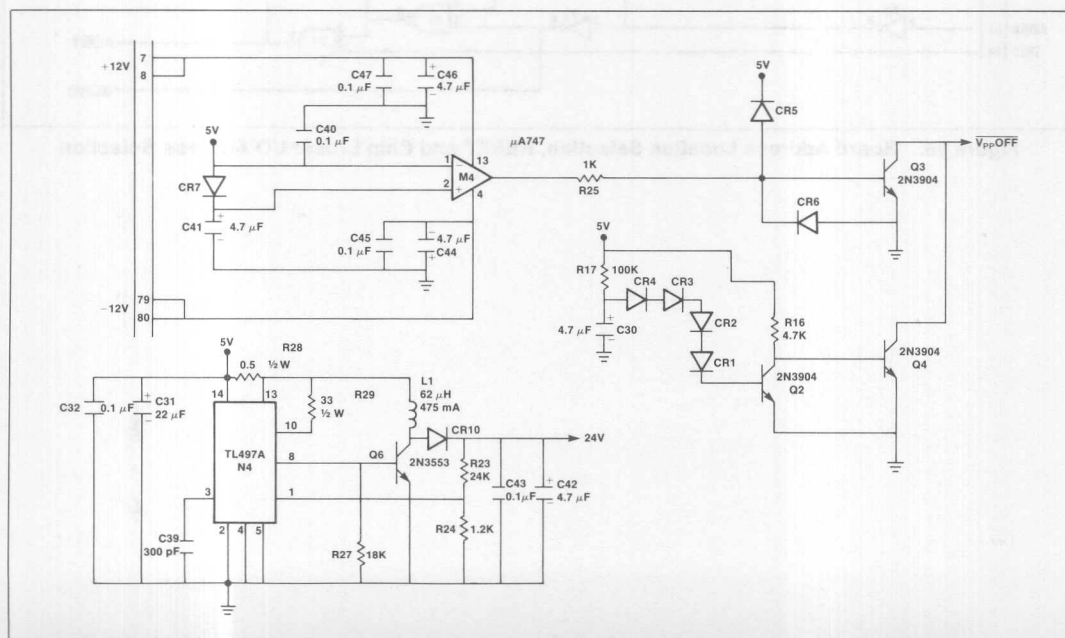
Figure 17. V_{pp} and OE Drivers

Figure 18. 5V to 23V Converter and Power Up/Power Down Write Protection Circuitry

ASSEMBLY INSTRUCTIONS

1. Install and solder the following Integrated Circuits:

A4 — 74S32	A2 — 74S04
B4 — 74S240	B2 — 74S00
D4 — 8283	C2 — 74S08
E4 — 8283	D2 — 74LS74
F4 — 8287	E2 — 74LS08
H4 — 8283	F2 — 74LS00
J4 — 8283	H2 — 74LS32
K4 — 8287	J2 — 74S30
A3 — 74S10	K2 — 7407
B3 — 74S05	A1 — 9602
C3 — 74LS85	B1 — PE-21216
D3 — 74LS85	C1 — 74LS393
E3 — 74LS85	D1 — 74LS74
F3 — 74LS04	E1 — 74LS74
J3 — 8286	F1 — 9602
	H1 — 9602
	L1 — 8282
	N4 — TL497A
	M4 — UA747
	P4 — LM358

2. Install and solder a 24-pin socket at K1.

3. Install and solder 28-pin sockets at M1, L2, N1, N2, P1, P2, R1 and R2.

4. Install and solder jumper pin pairs at the following locations:

J1	J5	J13	J16
J2	J6	J14	J17
J3	J7	J15	J18
J4	J8		J19
J9		J20	
J10			
J11			
J12			

5. Break in half 4 jumper pairs.

Install and solder one jumper pair at J21. Install and solder one of the single jumper pins at J22.

Install and solder another single jumper pin and one jumper pair at J23 and J24.

Install and solder jumper pairs at JW7, JW3, and JW2.

Install and solder single jumper pins at JW8, JW4, JW1, JW6, and JW5.

6. Install and solder the Dipswitch at location J1.

7. Install and solder resistors and resistor networks at the following locations:

H3 — 898-1-R1K	R16 — 4.7K
K3 — 898-1-R1K	R17 — 100K
RP1 — 784-1-R1K	R29 — 33, 1/2 W
RP2 — 784-1-R1K	R28 — 0.5, 1/2 W
RP3 — 784-1-R1K	R27 — 18K
RP4 — 784-1-R1K	R24 — 1.2K
RP5 — 784-1-R1K	R23 — 24K
R6 — 1K	R15 — 10K
R5 — 24K	R22 — 12K
R4 — 6.2K	R21 — 10K
R3 — 10K	R20 — 1.2K
R2 — 24K	R18 — 47K
R1 — 1K	R12 — 2K
R32 — 1K	R13 — 12K
R10 — 1K	R14 — 1K
R9 — 1K	R25 — 1K
R8 — 2K	
R19 — 5K	
	Mini-potentiometer
R31 — 1K	
R30 — 1K	

8. Install and solder capacitors in the following locations:

C13 — 0.1 μ f	C19 — 0.1 μ f
C12 — 0.1 μ f	C18 — 0.1 μ f
C11 — 0.1 μ f	C17 — 0.1 μ f
C10 — 0.1 μ f	C16 — 0.1 μ f
C9 — 0.33 μ f	C15 — 0.1 μ f
C8 — 4.7 μ f	C28 — 0.1 μ f
C7 — 20 pf	C27 — 0.1 μ f
C6 — 0.1 μ f	C26 — 0.1 μ f
C5 — 0.1 μ f	C25 — 0.1 μ f
C4 — 0.1 μ f	C24 — 0.1 μ f
C3 — 0.1 μ f	C37 — 0.1 μ f
C2 — 0.1 μ f	C49 — 22 μ f
C1 — 0.1 μ f	C36 — 0.1 μ f
C23 — 0.1 μ f	C35 — 0.1 μ f
C22 — 0.1 μ f	C34 — 0.1 μ f
C21 — 0.1 μ f	C33 — 0.1 μ f
C20 — 0.1 μ f	C48 — 22 μ f

9. Install and solder the following diodes:

CR1 — 1N914	CR7 — 1N914
CR2 — 1N914	CR8 — 1N4747A
CR3 — 1N914	CR9 — 1N914
CR4 — 1N914	CR10 — 1N914
CR5 — 1N914	CR11 — HP5082-2800
CR6 — 1N914	CR12 — 1N914

10. Install and solder the following transistors:

Q1 — 2N2222A
 Q2 — 2N3904
 Q3 — 2N3904
 Q4 — 2N3904
 Q5 — 2N3904
 Q6 — 2N3553

If hardware is provided or available, mount transistors in the following locations:

Q7 — 2N4923

Solder the leads of Q7 and Q8 to the solder pads on the board.

11. Install and solder the following capacitors:

C40 — 0.1 μ f C41 — 4.7 μ f
 C47 — 0.1 μ f C44 — 4.7 μ f
 C45 — 0.1 μ f C42 — 4.7 μ f
 C39 — 300 pf C31 — 22 μ f
 C43 — 0.1 μ f C30 — 4.7 μ f
 C38 — 0.05 μ f C46 — 4.7 μ f
 C32 — 0.1 μ f

12. Install and solder the 62 μ h RF choke at location L1 (just above the 60-pin edge connector).

APPENDIX A JUMPER LIST

J1 INT0
J2 INT1
J3 INT2
J4 INT3
J5 INT4
J6 INT5
J7 INT6
J8 INT7

J9 (ADR10) 4 bit selection of one of
J10 (ADR11) 16 64K pages for board
J11 (ADR12) address
J12 (ADR13) —Note: these ADRs are in HEX

J13 (ADR1)
J14 (ADR2)
J15 (ADR3) Select I/O address for Chip Erase
J16 (ADR4) Mode (ADR 0=1) and RESET function
J17 (ADR5) (ADR 0=0)
J18 (ADR6)
J19 (ADR7)

J20 Jumped for 16-bit wide data bus, Open for 8-bit wide data bus.

NOTE: The proper decoding algorithm for the data bus must be used in the BIPOLAR PROM decoder—refer to the PROM Array Address Configuration subsection of the Installation Instructions.

J21 (Select 4K/8K) MOS PROMs 1-4
J22 (Select 2K)

J23 (Select 4K/8K) MOS PROMs 5-8
J24 (Select 2K)

JW1 8-bit wide static RAM

JW2
JW3
JW4
JW5
JW6
JW7
JW8

APPENDIX B

BIP DECODER DATA FORMAT

3628A, 1K X 8, 000-3FFH

Data = all 1's at all locations not shown.

0 = Switch is on

1 = Switch is off

SW4	SW3	SW2	SW1	(Hex) Address	(Hex) Data	Decoding for
0	0	0	0	2 3 6 7 A B E F	FE FD FB F7 EF DF BF 7F	2K X 8 (2816, 2815 OR 2716) 8-BIT DATA BUS
0	0	0	1	42 43 46 47 4A 4B 4E 4F 52 53 56 57 5A 5B 5E 5F	FE FD FE FD FB F7 FB F7 EF DF EF DF BF 7F BF 7F	4K X 8 (2732, 2732A) 8-BIT DATA BUS
0	0	1	0	82 83 86 87 8A 8B 8E 8F 92 93 96 97 9A 9B 9E 9F A2 A3 A6 A7 AA AB AE AF B2 B3	FE FD FE FD FE FD FE FD FB F7 FB F7 FB F7 FB F7 EF DF EF DF EF DF EF DF BF BF 7F	8K X 8 (2764) 8-BIT DATA BUS

SW4	SW3	SW2	SW1	(Hex) Address	(Hex) Data	Decoding for
0	0	1	0	B6 B7 BA BB BE BF	BF 7F BF 7F BF 7F	8K X 8 8-BIT DATA BUS (Continued)
0	0	1	1	C0 C1 C2 C4 C5 C6 C8 C9 CA CC CD CE	FC FD FE F3 F7 FB CF DF EF 3F 7F BF	2K X 8 16-BIT DATA BUS (2816, 2815, OR 2716)
0	1	0	0	100 101 102 104 105 106 108 109 10A 10C 10D 10E 110 111 112 114 115 116 118 119 11A 11C 11D 11E	FC FD FE FC FD FE F3 F7 FB F3 F7 FB CF DF EF CE DF EF 3F 7F BF 3F 7F BF	4K X 8 16-BIT DATA BUS (2732 OR 2732A)
0	1	0	1	140 141 142 144 145 146 148 149 14A 14C 14D 14E 150 151 152 154 155 156	FC FD FE FC FD FE FC FD FE FC FD FE F3 F7 FB F3 F7 FB	8K X 8 16-BIT DATA BUS (2764)

SW4	SW3	SW2	SW1	(Hex) Address	(Hex) Data	Decoding for
0	1	0	1	158 159 15A 15C 15D 15E 160 161 162 164 165 166 168 169 16A 16C 16D 16E 170 171 172 174 175 176 178 179 17A 17C 17D 17E	F3 F7 FB F3 F7 FB CF DF EF CF DF EF CF DF EF CF DF EF 3F 7F BF 3F 7F BF 3F 7F BF	8K × 8 16-BIT DATA BUS (Continued)
0	1	1	0	1A2 1A3 1A6 1A7 1AA 1AB 1AE 1A7	FE FD FB F7 EF DF BF 7F	LOCATED AT 8000H 8-BIT DATA BUS (2716, 2816 OR 2815)
0	1	1	1	1E0 1E1 1E2 1E4 1E5 1E6 1E8 1E9 1EA 1EC 1ED 1EE	FC FD FE F3 F7 FB CF DF EF 3F 7F BF	LOCATED AT 8000H 16-BIT DATA BUS (2716, 2816 OR 2815)

APPENDIX C PARTS LIST

Table C-1. Integrated Circuits

Qty	Description
1	3628A-4
4	8283
1	8286
2	8287
3	74LS85
1	74LS393
3	9602
3	74LS74
1	74LS08
1	74S10
1	74S30
1	74LS32
1	74LS04
1	74LS00
1	74S00
1	74S05
1	8282
1	74S08
1	74S04
1	74S32
1	74S240
1	LM358
1	TTL Delay Line PE-21216
1	μ A747
1	7407
1	TL497A
36	TOTAL

Table C-3. Discrete Components

Qty	Description
1	Cap., 20 pf
1	Cap., 50 pf
2	Resistor, 12K
1	Cap., 0.33 μ f
1	Cap., 0.05 μ f
1	Resistor, 47K
1	Resistor, 6.2K
2	Resistor, 2K
3	Resistor, 10K
6	Cap., 4.7 μ f
1	Mini-potentiometer, TrimPot 3009p-1-502, 5K
2	Resistor, 1.2K
3	Resistor, 24K
1	Resistor, 18K
1	Resistor, 33, 1/2W
1	Resistor, 0.5, 1/2W
34	Cap., 0.1 μ f, 50V, ceramic
3	Cap., 22 μ f, 25V
1	Cap., 300 pf
1	Resistor, 100K
1	Resistor, 4.7K
9	Resistor, 1K

Table C-2. Discrete Components

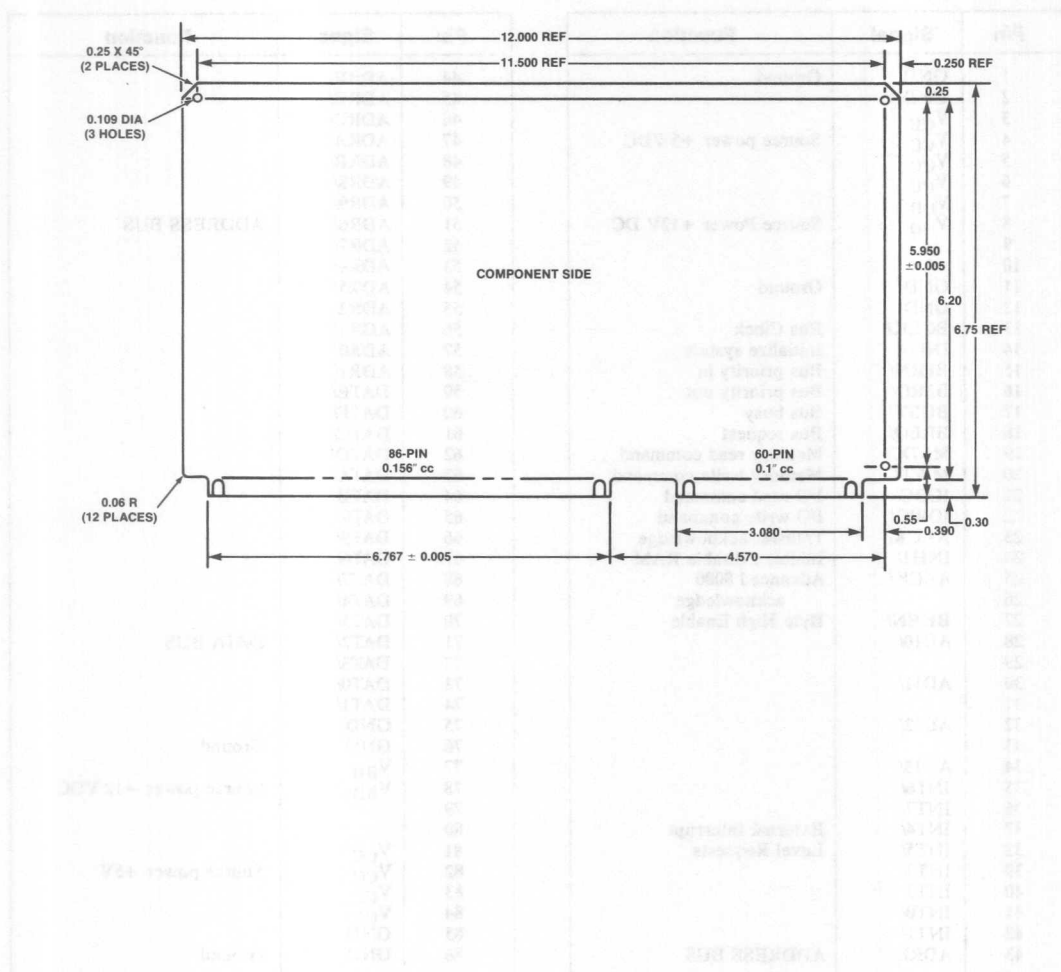
Qty	Description
1	2N3553
1	2N4923
4	2N3904
1	2N2222A
11	1N914
1	HP5082-2800 (Schottky Diode)
1	1N4747A
1	R.F. Choke, 62 μ h, 475 ma
	J.W. Miller 4630
5	Resistor Network Beckman 784-1-R1K
2	Resistor Network Beckman 898-1-R1K
1	Dip Switch, CTS 206-8
1	24-Pin Socket
8	28-Pin Sockets
29	Header Pins
18	Shorting Plugs

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APPENDIX E

MULTIBUS PCB DIMENSIONS



APPENDIX F

MULTIBUS SIGNAL LIST

Pin	Signal	Function	Pin	Signal	Function
1	GND	Ground	44	ADRF/	ADDRESS BUS
2	GND		45	ADRC/	
3	V _{CC}	Source power +5 VDC	46	ADRD/	
4	V _{CC}		47	ADRA/	
5	V _{CC}		48	ADRB/	
6	V _{CC}		49	ADR8/	
7	V _{DD}	Source Power +12V DC	50	ADR9/	
8	V _{DD}		51	ADR6/	
9	V _{DD}		52	ADR7/	
10			53	ADR4/	
11	GND	Ground	54	ADR5/	DATA BUS
12	GND		55	ADR2/	
13	BCLK/	Bus Clock	56	ADR3/	
14	INIT/	Initialize system	57	ADR0/	
15	BPRN/	Bus priority in	58	ADR1/	
16	BPRO/	Bus priority out	59	DATE/	
17	BUSY/	Bus busy	60	DATF/	
18	BREQ/	Bus request	61	DATC/	
19	MRDC/	Memory read command	62	DATD/	
20	MWTC/	Memory write command	63	DATA/	
21	IORC/	I/O read command	64	DATB/	
22	IOWC/	I/O write command	65	DAT8/	
23	XACK/	Transfer acknowledge	66	DAT9/	
24	INH1/	Inhibit 1 disable RAM	67	DAT6/	
25	AACK/	Advanced 8080 acknowledge	68	DAT7/	
26			69	DAT4/	
27	BHEN/	Byte High Enable	70	DAT5/	
28	AD10/		71	DAT2/	
29			72	DAT3/	
30	AD11/		73	DAT0/	
31			74	DAT1/	
32	AD12/		75	GND	Ground
33			76	GND	
34	AD13/		77	V _{BB}	Source power -12 VDC
35	INT6/		78	V _{BB}	
36	INT7/		79		Source power +5V
37	INT4/	External Interrupt Level Requests	80		
38	INT5/		81	V _{CC}	
39	INT2/		82	V _{CC}	
40	INT3/		83	V _{CC}	Ground
41	INT0/		84	V _{CC}	
42	INT1/		85	GND	
43	ADRE/	ADDRESS BUS	86	GND	

APPENDIX G BLANK DECODER CHARTS

SYSTEM ADDRESS A0-15 HEX	DECODER CIRCUIT INPUTS						CE'S								BYTE	
	BAF	BAE	BAD	BAC	BHEN	LA0	7	6	5	4	3	2	1	0		
0 X X X	0	0	0	0	1 1	0 1										L H
1 X X X	0	0	0	1	1 1	0 1										L H
2 X X X	0	0	1	0	1 1	0 1										L H
3 X X X	0	0	1	1	1 1	0 1										L H
4 X X X	0	1	0	0	1 1	0 1										L H
5 X X X	0	1	0	1	1 1	0 1										L H
6 X X X	0	1	1	0	1 1	0 1										L H
7 X X X	0	1	1	1	1 1	0 1										L H
8 X X X	1	0	0	0	1 1	0 1										L H
9 X X X	1	0	0	1	1 1	0 1										L H
A X X X	1	0	1	0	1 1	0 1										L H
B X X X	1	0	1	1	1 1	0 1										L H
C X X X	1	1	0	0	1 1	0 1										L H
D X X X	1	1	0	1	1 1	0 1										L H
E X X X	1	1	1	0	1 1	0 1										L H
F X X X	1	1	1	1	1 1	0 1										L H
X=HEX DIGITS	A5	A4	A3	A2	A1	A0	0 7	0 6	0 5	0 4	0 3	0 2	0 1	0 0		
ADDRESS INPUTS 3628A							OUTPUTS									

L = LOW BYTE
H = HIGH BYTE
0 = ENABLE
1 = DISABLE

0 = NO SHORTING PLUG
X = SHORTING PLUG INSTALLED

8 BIT DATA BUS

LEAVE JUMPER J20 OPEN. (NO SHORTING PLUG)

INSTALL SHORTING PLUGS
PER THE FOLLOWING TABLE:
DEVICE DENSITY = K BYTES

JUMPERS			
PROMS:			
1-4		5-8	
2K	J21 0	J22 X	J23 0
4K/8K	X	0	X

SYSTEM ADDRESS A0-15 HEX	DECODER CIRCUIT INPUTS						$\overline{\text{CE}}\text{'S}$								BYTE
	BAF	BAE	BAD	BAC	BHEN	LA0	7	6	5	4	3	2	1	0	
0XXX	0	0	0	0	0 1 0	0 0 1									W L H
1XXX	0	0	0	1	0 1 0	0 0 1									W L H
2XXX	0	0	1	0	0 1 0	0 0 1									W L H
3XXX	0	0	1	1	0 1 0	0 0 1									W L H
4XXX	0	1	0	0	0 1 0	0 0 1									W L H
5XXX	0	1	0	1	0 1 0	0 0 1									W L H
6XXX	0	1	1	0	0 1 0	0 0 1									W L H
7XXX	0	1	1	1	0 1 0	0 0 1									W L H
8XXX	1	0	0	0	0 1 0	0 0 1									W L H
9XXX	1	0	0	1	0 1 0	0 0 1									W L H
AXXX	1	0	1	0	0 1 0	0 0 1									W L H
BXXX	1	0	1	1	0 1 0	0 0 1									W L H
CXXX	1	1	0	0	0 1 0	0 0 1									W L H
DXXX	1	1	0	1	0 1 0	0 0 1									W L H
EXXX	1	1	1	0	0 1 0	0 0 1									W L H
FXXX	1	1	1	1	0 1 0	0 0 1									W L H
X = HEX DIGITS	A5	A4	A3	A2	A1	A0	0 7	0 6	0 5	0 4	0 3	0 2	0 1	0 0	
	ADDRESS INPUTS 3628A						OUTPUTS								

L = LOW BYTE
H = HIGH BYTE
0 = ENABLE
1 = DISABLE
0 = NO SHORTING PLUG
X = SHORTING PLUG INSTALLED

16 BIT DATA BUS

INSTALL SHORTING PLUG AT JUMPER J20.

INSTALL SHORTING PLUGS
PER THE FOLLOWING TABLE:

DEVICE DENSITY = K BYTES

JUMPERS			
PROMS:			
1-4		5-8	
J21	J22	J23	J24
0	X	0	X
2K	X	0	X
4K/8K	X	0	X

APPENDIX H TEST DECODING ALGORITHMS FOR 2K X 8 MOS PROMs AT 8000H

SYSTEM ADDRESS A0-15 HEX	DECODER CIRCUIT INPUTS						$\overline{\text{CE}}$ 'S										BYTE
	BAF	BAE	BAD	BAC	BHEN	LA0	7	6	5	4	3	2	1	0			
0 X X X	0	0	0	0	1 1	0 1											L H
1 X X X	0	0	0	1	1 1	0 1											L H
2 X X X	0	0	1	0	1 1	0 1											L H
3 X X X	0	0	1	1	1 1	0 1											L H
4 X X X	0	1	0	0	1 1	0 1											L H
5 X X X	0	1	0	1	1 1	0 1											L H
6 X X X	0	1	1	0	1 1	0 1											L H
7 X X X	0	1	1	1	1 1	0 1											L H
8 X X X	1	0	0	0	1 1	0 1									0	0	L H
9 X X X	1	0	0	1	1 1	0 1							0				L H
A X X X	1	0	1	0	1 1	0 1				0	0						L H
B X X X	1	0	1	1	1 1	0 1	0	0									L H
C X X X	1	1	0	0	1 1	0 1											L H
D X X X	1	1	0	1	1 1	0 1											L H
E X X X	1	1	1	0	1 1	0 1											L H
F X X X	1	1	1	1	1 1	0 1											L H
X - HEX DIGITS	A5	A4	A3	A2	A1	A0	0 7	0 6	0 5	0 4	0 3	0 2	0 1	0 0			
ADDRESS INPUTS 3628A							OUTPUTS										

L = LOW BYTE
H = HIGH BYTE

0 = ENABLE
1 = DISABLE

0 = NO SHORTING PLUG
X = SHORTING PLUG INSTALLED

8 BIT DATA BUS

LEAVE JUMPER J20 OPEN. (NO SHORTING PLUG)

INSTALL SHORTING PLUGS
PER THE FOLLOWING TABLE:

DEVICE DENSITY = 2K BYTES

JUMPERS

PROMS:

	1-4		5-8	
	J21	J22	J23	J24
2K	0	X	0	X
4K/8K	X	0	X	0

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SYSTEM ADDRESS A0-15 HEX	DECODER CIRCUIT INPUTS						\overline{CE} 'S										BYTE
	BAF	BAE	BAD	BAC	BHEN	LA0	7	6	5	4	3	2	1	0			
0XXX	0	0	0	0	0 1 0	0 0 1									W L H		
1XXX	0	0	0	1	0 1 0	0 0 1									W L H		
2XXX	0	0	1	0	0 1 0	0 0 1									W L H		
3XXX	0	0	1	1	0 1 0	0 0 1									W L H		
4XXX	0	1	0	0	0 1 0	0 0 1									W L H		
5XXX	0	1	0	1	0 1 0	0 0 1									W L H		
6XXX	0	1	1	0	0 1 0	0 0 1									W L H		
7XXX	0	1	1	1	0 1 0	0 0 1									W L H		
8XXX	1	0	0	0	0 1 0	0 0 1							0 0 0	0 0	W L H		
9XXX	1	0	0	1	0 1 0	0 0 1					0 0 0		0 0		W L H		
AXXX	1	0	1	0	0 1 0	0 0 1			0 0 0	0 0 0					W L H		
BXXX	1	0	1	1	0 1 0	0 0 1	0 0 0	0 0 0							W L H		
CXXX	1	1	0	0	0 1 0	0 0 1									W L H		
DXXX	1	1	0	1	0 1 0	0 0 1									W L H		
EXXX	1	1	1	0	0 1 0	0 0 1									W L H		
FXXX	1	1	1	1	0 1 0	0 0 1									W L H		
X = HEX DIGITS	A5	A4	A3	A2	A1	A0	0 7	0 6	0 5	0 4	0 3	0 2	0 1	0 0	OUTPUTS		

L = LOW BYTE
H = HIGH BYTE
0 = ENABLE
1 = DISABLE
0 = NO SHORTING PLUG
X = SHORTING PLUG INSTALLED

16 BIT DATA BUS

INSTALL SHORTING PLUG AT JUMPER J20.

INSTALL SHORTING PLUGS
PER THE FOLLOWING TABLE:

DEVICE DENSITY 2K BYTES

JUMPERS			
PROMS:			
1-4		5-8	
2K	J21 0	J22 X	J23 0
4K/8K	X	0	X